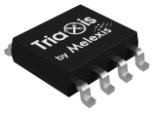


# MLX90425

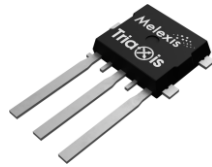
Triaxis® Position Sensor IC  
Datasheet

## Features and Benefits

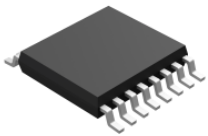
- Triaxis® Hall Technology
- On-Chip Signal Processing for Robust Absolute Position Sensing
- **ASIL READY** BY MELEXIS ISO26262 ASIL-B Safety Element out of Context
- AEC-Q100 Qualified (Grade 0)
- Robust to external magnetic stray fields
- Programmable Measurement Range
- Programmable Linear Transfer Characteristic up to 17 points
- Ratiometric analog or PWM output
- Packages RoHS compliant
  - Single Die SOIC-8
  - PCB-less Single Die SMP-3
  - TSSOP-16\_EP package (stacked-dice)
  - SMP-4 package (stacked-dice)



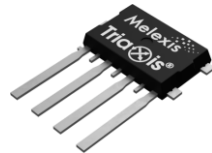
SOIC-8 (DC)



SMP-3 (VE)



TSSOP-16\_EP (GO)



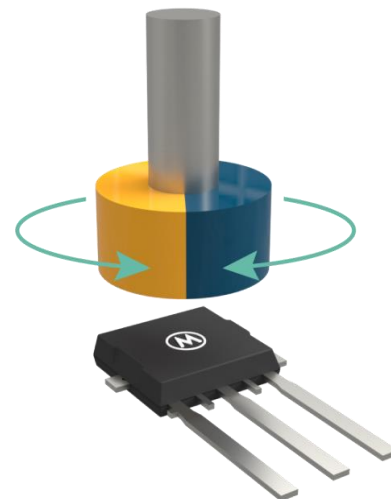
SMP-4 (VD)

## Description

The MLX90425 is a monolithic magnetic position sensor IC. It consists of a Triaxis® Hall magnetic front end, an analog-to-digital signal conditioner, a DSP for advanced signal processing and a programmable output stage driver.

The MLX90425 is sensitive to the differential magnetic field perpendicular to the IC surface (Z-axis). This allows the MLX90425, with the correct magnetic design, to decode the absolute position of a rotating on-axis magnet above or below the sensor (e.g. rotary position from 0° to 360°). It enables the design of non-contacting position sensors that are frequently required in automotive and industrial applications.

The MLX90425 provides either a ratiometric analog or a pulse width modulated (PWM) output. Programming the sensor, after assembly into the application, increases the accuracy of the system thanks to the multi-point programmable linearization function.



Angular Rotary – 360° Stray field Robust

## Application Examples

- Pedal Position Sensor
- Throttle Position Sensor
- Ride Height Position Sensor
- Transmission Position Sensor
- Steering Wheel Position Sensor
- Non-Contacting Potentiometer

## Ordering Information

Product	Temp.	Package	Option Code	Packing Form	Definition
MLX90425	G	DC	ABA-600	RE	Angular Rotary 360° Stray field Robust Analog / PWM version
MLX90425	G	VE	ABA-600	RE/RX	Angular Rotary 360° Stray field Robust Analog / PWM version
MLX90425	G	GO	BAA-600	RE	Angular Rotary 360° Stray field robust Analog/PWM version / Stacked-dice in TSSOP-16
MLX90425	G	VD	BAA-600	RE	Angular Rotary 360° Stray field robust Analog/PWM version / Stacked-dice in SMP4

Table 1 – Ordering codes

Temperature Code:	G : from -40°C to 160°C Some parts can be exposed to higher temperatures for a limited time <sup>(1)</sup>
Package Code:	DC: SOIC-8 package (see 17.1) VE: SMP-3 package (PCB-less single mold, see 17.2) GO: TSSOP-16_EP package (see 17.3) VD: SMP-4 package (PCB-less single mold, see 17.4)
Option Code - Chip revision	<b>AAA-123 : Chip Revision</b> <ul style="list-style-type: none"> <li>ABA: MLX90425 Single Die production version</li> <li>BAA: MLX90425 Stacked Dice production version</li> </ul>
Option Code - Application	<b>AAA-123 : 1-Application - Magnetic configuration</b> <ul style="list-style-type: none"> <li>6: Angular Rotary 360° Stray field Robust</li> </ul>
Option Code	<b>AAA-123 : 2-Programming Option</b> <ul style="list-style-type: none"> <li>0: Standard (Analog output) programmable to PWM</li> </ul>
Option Code - Trim & Form	<b>AAA-123 : 3-Package Option</b> <ul style="list-style-type: none"> <li>0: Standard</li> </ul>
Packing Form:	-RE : Tape & Reel <ul style="list-style-type: none"> <li>VE: 2500 pcs/reel</li> <li>DC: 3000 pcs/reel</li> <li>GO: 4500 pcs/reel</li> <li>VD: 2500 pcs/reel</li> </ul> -RX : Tape & Reel, similar to RE with parts face-down
Ordering Example:	MLX90425GDC-ABA-600-RE For an analog version in SOIC-8 package, delivered in reels of 3000pcs.

Table 2 – Ordering codes information

<sup>1</sup> The devices can be used up to an ambient temperature of +180°C. For a description of the conditions, refer to the sub-sections labelled "High-temperature Extension"(4.1, 5.1, 8.2.1, 10.1.1, 10.2.3, 12.5.4).

# Contents

<b>Features and Benefits</b> .....	<b>1</b>
<b>Application Examples</b> .....	<b>1</b>
<b>Description</b> .....	<b>1</b>
<b>Ordering Information</b> .....	<b>2</b>
<b>1. Functional Diagram and Application Modes</b> .....	<b>5</b>
<b>2. Glossary of Terms</b> .....	<b>6</b>
<b>3. Pin Definitions and Descriptions</b> .....	<b>7</b>
3.1. Pin Definition for SOIC-8.....	7
3.2. Pin Definition for SMP-3 .....	7
3.3. Pin Definition for TSSOP-16_EP .....	8
3.4. Pin Definition for SMP-4 .....	8
<b>4. Absolute Maximum Ratings</b> .....	<b>9</b>
4.1. High-Temperature Extension Absolute Maximum Ratings .....	9
4.2. Isolation Specification.....	10
<b>5. General Electrical Specifications</b> .....	<b>10</b>
5.1. High-Temperature Extension Electrical Specifications .....	12
<b>6. Timing Specifications</b> .....	<b>13</b>
6.1. General Timing Specifications .....	13
6.2. Continuous Acquisition Mode .....	13
6.3. Timing Definitions.....	14
6.4. Analog Output Timing Specifications.....	16
6.5. PWM Output Timing Specifications .....	16
<b>7. Magnetic Field Specifications</b> .....	<b>17</b>
7.1. Magnetic Field Specifications for MLX90425 Single Die .....	17
7.2. Magnetic Field Specifications for MLX90425 Stacked Dice .....	18
<b>8. Accuracy Specifications</b> .....	<b>19</b>
8.1. Definitions .....	19
8.2. Single die performances .....	20
8.3. Stacked dice performances .....	21
<b>9. Memory Specifications</b> .....	<b>22</b>
<b>10. Output Protocol Description</b> .....	<b>22</b>
10.1. Analog Output Description .....	22
10.2. PWM Output Description .....	23

<b>11. End-User Programmable Items.....</b>	<b>24</b>
<b>12. Description of End-User Programmable Items .....</b>	<b>28</b>
12.1. Output modes and protocols.....	28
12.2. Output Transfer Characteristic .....	28
12.3. Sensor Front-End .....	33
12.4. Filtering.....	34
12.5. Programmable Diagnostics Settings .....	35
<b>13. Functional Safety .....</b>	<b>38</b>
13.1. Safety Manual.....	38
13.2. Safety Mechanisms.....	38
13.3. Fault Handling Time Interval.....	42
<b>14. Recommended Application Diagrams .....</b>	<b>42</b>
14.1. Wiring with the MLX90425 in SOIC-8 Package .....	42
14.2. Wiring with the MLX90425 in SMP-3 Package (built-in capacitors) .....	43
14.3. Wiring with the MLX90425 in TSSOP-16_EP Package.....	44
14.4. Wiring with the MLX90425 in SMP-4 Package (built-in capacitors) .....	45
<b>15. Standard information regarding manufacturability of Melexis products with different soldering processes.....</b>	<b>46</b>
15.1. Soldering recommendations for the Exposed Pad (EP) in TSSOP-16.....	46
<b>16. ESD Precautions.....</b>	<b>46</b>
<b>17. Package Information .....</b>	<b>47</b>
17.1. SOIC-8 – Package Information .....	47
17.2. SMP-3 – Package Information .....	49
17.3. TSSOP-16_EP .....	52
17.4. SMP-4 Package Information .....	55
17.5. Packages Thermal Performances.....	58
<b>18. Contact .....</b>	<b>59</b>
<b>19. Disclaimer .....</b>	<b>59</b>

# 1. Functional Diagram and Application Modes

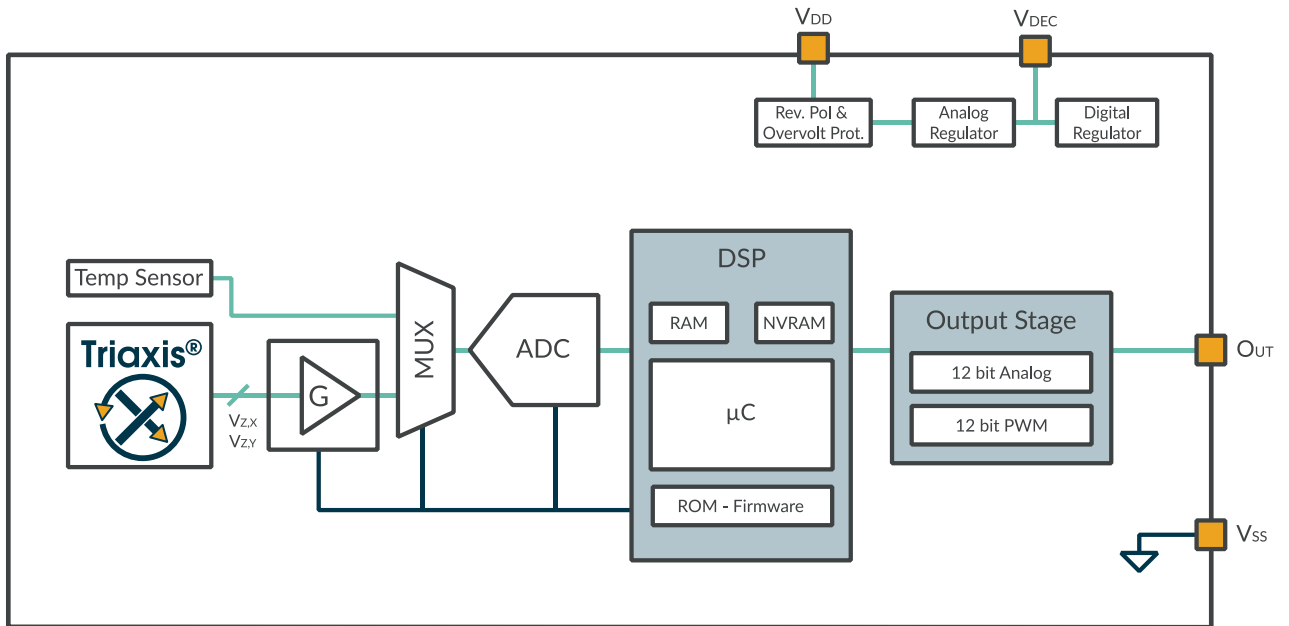


Figure 1 - MLX90425 Single Die and Stacked Dice Block diagrams.

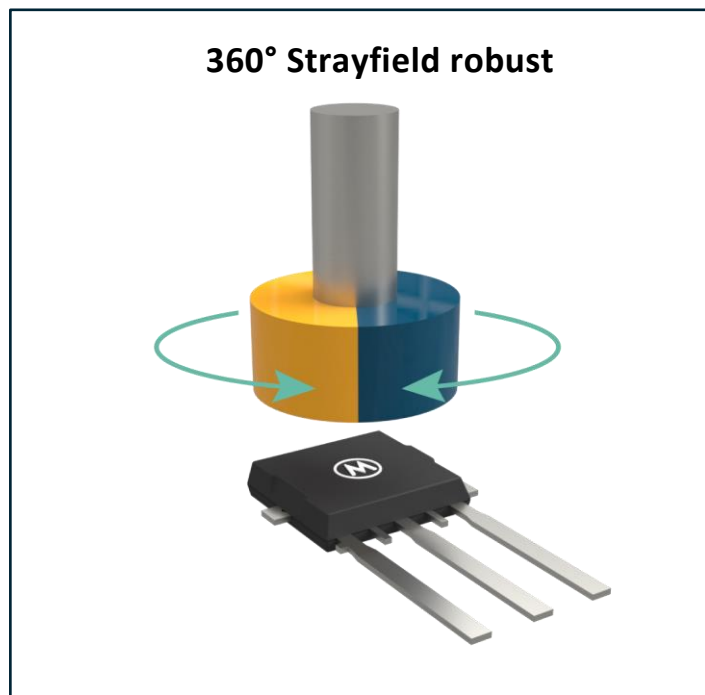


Figure 2 – Application mode

## 2. Glossary of Terms

Name	Description
ADC	Analog-to-Digital Converter
AWD	Absolute Watchdog
CPU	Central Processing Unit
CRC	Cyclic Redundancy Check
DAC	Digital-to-Analog Converter
%DC	Duty Cycle of the output signal i.e. $T_{ON} / (T_{ON} + T_{OFF})$
DP	Discontinuity Point
DCT	Diagnostic Cycle Time
DSP	Digital Signal Processing
ECC	Error Correcting Code
EMC	Electro-Magnetic Compatibility
EoL	End of Line
FHTI	Fault Handling Time Interval
FIR	Finite Impulse Response
Gauss (G)	Alternative unit for the magnetic flux density (10G = 1mT)
HW	Hardware
IMC	Integrated Magnetic Concentrator
INL / DNL	Integral Non-Linearity / Differential Non-Linearity
IWD	Intelligent Watchdog
LNR	LiNearRization
LSB / MSB	Least Significant Bit / Most Significant Bit
N.C.	Not Connected
NVRAM	Non-Volatile RAM
PCB	Printed Circuit Board
POR	Power-On Reset
PSF	Product Specific Functions
PWL	Piecewise Linear
PWM	Pulse Width Modulation
RAM	Random Access Memory
ROM	Read-Only Memory
SEooC	Safety Element out of Context
SMP	Single-Mold Package with integrated discrete components (capacitors)
TC	Temperature Coefficient (generally in ppm/°C)
Tesla (T)	SI-derived unit for the magnetic flux density (Vs/m <sup>2</sup> )
TSSOP-16_EP	TSSOP-16 Exposed Pad

*Table 3 – Glossary of terms*

## 3. Pin Definitions and Descriptions

### 3.1. Pin Definition for SOIC-8

Pin #	Name	Description
1	V <sub>DD</sub>	Supply
2	Test <sub>1</sub>	For Melexis factory test
3	Test <sub>2</sub>	For Melexis factory test
4	N.C.	Not connected
5	OUT	Output
6	N.C.	Not connected
7	V <sub>DEC</sub>	Decoupling pin
8	V <sub>SS</sub>	Ground

*Table 4 – SOIC-8 pins definition and description*

Test pins are internally grounded when in application mode. For optimal EMC behavior connect the Test and N.C. pins to the ground of the PCB.

### 3.2. Pin Definition for SMP-3

SMP-3 package offers advanced components integration in a single mold compact form.

Pin #	Name	Description
1	V <sub>DD</sub>	Supply
2	OUT	Output
3	V <sub>SS</sub>	Ground

*Table 5 – SMP-3 pins definition and description*

### 3.3. Pin Definition for TSSOP-16\_EP

Pin #	Name	Description
1	N.C.	Not connected
2	V <sub>DEC1</sub>	Decoupling pin die 1 <sup>(2)</sup>
3	OUT <sub>1</sub>	Output die 1
4	Test <sub>11</sub>	For Melexis factory test
5	V <sub>SS1</sub>	Ground die 1
6	V <sub>DD1</sub>	Supply die 1
7	Test <sub>21</sub>	For Melexis factory test
8	N.C.	Not connected
9	V <sub>DEC2</sub>	Decoupling pin die 2 <sup>(3)</sup>
10	N.C.	Not connected
11	OUT <sub>2</sub>	Output die 2
12	Test <sub>12</sub>	For Melexis factory test
13	V <sub>SS2</sub>	Ground die 2
14	V <sub>DD2</sub>	Supply die 2
15	Test <sub>22</sub>	For Melexis factory test
16	N.C.	Not connected

*Table 6 – TSSOP-16\_EP Pin definition and description*

Test pins are internally grounded when in application mode. For optimal EMC behavior connect the Test and N.C. pins to the ground of the PCB.

### 3.4. Pin Definition for SMP-4

SMP-4 package offers a redundant stacked-dice package with advanced components integration in a single mold compact form.

Pin #	Name	Description
1	OUT1	Output (die 1)
2	V <sub>SS</sub>	Ground (common to die 1 <sup>(2)</sup> and die 2 <sup>(3)</sup> )
3	V <sub>DD</sub>	Supply (common to die 1 and die 2)
4	OUT2	Output (die 2)

*Table 7 – SMP-4 Pin definition and description*

<sup>(2)</sup> Die 1 – bottom die.

<sup>(3)</sup> Die 2 – top die.

## 4. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Condition
Supply Voltage	Positive	$V_{DD}$		28 37	V < 48h < 60s; $T_{AMB} \leq 35^{\circ}\text{C}$
	Reverse	$V_{DD\text{-rev}}$	-14 -18		V < 48h < 1h
Positive Output Voltage	Positive	$V_{OUT}$		28 34	V < 48h < 1h
	Reverse	$V_{OUT\text{-rev}}$	-14 -18		V < 48h < 1h
Internal Voltage	Positive	$V_{DEC}$		3.6	V < 1h
	Reverse	$V_{DEC\text{-rev}}$	-0.3		V < 1h
Positive Test <sub>1</sub> pin Voltage	Positive	$V_{Test1}$		6	V < 1h
	Reverse	$V_{Test1\text{-rev}}$	-3		V < 1h
Positive Test <sub>2</sub> pin Voltage	Positive	$V_{test2}$		3.6	V < 1h
	Reverse	$V_{test2\text{-rev}}$	-0.3		V < 1h
Operating Temperature	$T_{AMB}$	-40	+160	$^{\circ}\text{C}$	
Junction Temperature <sup>(4)</sup>	$T_J$		+175	$^{\circ}\text{C}$	
Storage Temperature	$T_{ST}$	-55	+170	$^{\circ}\text{C}$	
Magnetic Flux Density	$B_{max}$	-1	1	T	

Table 8 – Absolute maximum ratings

Exceeding any of the absolute maximum ratings may cause permanent damage. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

### 4.1. High-Temperature Extension Absolute Maximum Ratings

The MLX90425 can be exposed to high temperature within the range [160, 180]°C for a limited duration. The device continues to operate with degraded performances according to the values listed in the following table. This extension is only valid for the SMP-3 and SMP-4 packages.

Parameter	Symbol	Min	Max	Unit	Condition
Supply Voltage <sup>(5)</sup>	$V_{DD}$		5.5	V	$T_{AMB} = 180^{\circ}\text{C}$
Reverse Voltage Protection	$V_{DD\text{-rev}}$	-14		V	$T_{AMB} = 180^{\circ}\text{C}$ , < 1h
Positive Output Voltage	$V_{OUT}$		26	V	$T_{AMB} = 180^{\circ}\text{C}$ , < 1h
Reverse Output Voltage	$V_{OUT\text{-rev}}$	-14		V	$T_{AMB} = 180^{\circ}\text{C}$ , < 1h
Operating Temperature	$T_{AMB}$	-40	180	$^{\circ}\text{C}$	< 250h
Junction Temperature	$T_J$		190	$^{\circ}\text{C}$	< 250h
Storage Temperature	$T_{ST}$	-55	190	$^{\circ}\text{C}$	< 250h

Table 9 – High-temperature extension absolute maximum ratings for SMP-3 and SMP-4.

Exceeding any of the absolute maximum ratings may cause permanent damage. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

<sup>4</sup> Find package thermal dissipation values in section 17.2

<sup>5</sup> Higher supply voltages will increase the die temperature above the max junction temperature  $T_J$ .

## 4.2. Isolation Specification

Valid for the TSSOP-16\_EP packages.

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Isolation Resistance	$R_{isol}$	4	-	-	M $\Omega$	Between dice

Table 10 – Isolation resistance

## 5. General Electrical Specifications

General electrical specifications are valid for temperature range [-40, 160] °C and supply voltage range [4.5, 5.5] V unless otherwise noted.

Electrical Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Supply Voltage	$V_{DD}$	4.5	5	5.5	V	
Supply Current	$I_{DD}$	8	10	11.5	mA	Single Die
		17	20	24	mA	Stacked Dice <sup>(6)</sup>
Start-up Level (rising)	$V_{DDstartH}$	3.85	4.00	4.15	V	
Start-up Hysteresis	$V_{DDstartHyst}$		100		mV	
PTC Entry Level (rising)	$V_{PROVO}$	5.85	6.05	6.25	V	Supply overvoltage detection
PTC Entry Level Hysteresis	$V_{PROVOHyst}$	100	175	250	mV	
Under voltage detection	$V_{DDUVL}$	3.75	3.90	4.05	V	Supply voltage low threshold
Under voltage detection hysteresis	$V_{DDUVHyst}$		100		mV	
Regulated Voltage	$V_{DEC}$	3.2	3.3	3.4	V	Internal analog voltage

Table 11 – Supply system electrical specifications

<sup>6</sup>The stacked dice configuration necessitates minor design alterations to facilitate dice stacking, including the duplication of a subset of pads. These adjustments result in a minimal increase in current consumption per die.

Electrical Parameter	Symbol	Min	Typ.	Max	Unit	Condition
External Pull-up Voltage	$V_{ext}$			18	V	Output Pull-up voltage in open-drain NMOS mode or analog mode
				$V_{DD}$		Output Pull-up voltage in digital Push-Pull mode
Output Short-Circuit Current Limit	$I_{OUTshort}$	10		35	mA	
Output Load	$R_L$	5	10		k $\Omega$	Analog output
		5		100	k $\Omega$	Digital output in Push-Pull mode PWM pull-up to $V_{ext} = V_{DD}$ , PWM pull-down to 0V
		1.5		25		Digital output in open-drain mode PMOS, pull-down to 0V
		5		18	k $\Omega$	NMOS, pull-up to $V_{ext} \leq 18V$
		1.5		25		NMOS, pull-up to $V_{ext} = V_{DD}$
Analog output Saturation Level <sup>(7)</sup>	$V_{satA\_lo}$		0.5	1.2	% $V_{DD}$	Pull-up to $V_{ext}$ $R_L \geq 10\text{ k}\Omega$ , $V_{ext} \leq V_{DD}$
			3.3	7.4		$R_L \geq 5\text{ k}\Omega$ to $V_{ext} \leq 18V$
	$V_{satA\_hi}$	97.0	99.0		% $V_{DD}$	Pull-down to 0V $R_L \geq 10\text{ k}\Omega$
		95.0	98.0			$R_L \geq 5\text{ k}\Omega$
Digital output level push-pull mode <sup>(8)</sup>	$V_{satD\_lopp}$			1.2	% $V_{DD}$	Pull-up to $V_{ext} \leq V_{DD}$ , $R_L \geq 10\text{ k}\Omega$
	$V_{satD\_hipp}$	97.0			% $V_{DD}$	Pull-down to 0V, $R_L \geq 10\text{ k}\Omega$
		95.0				Pull-down to 0V, $R_L \geq 5\text{ k}\Omega$
Digital output level open-drain mode	$V_{satLoOd}$	0		10	% $V_{ext}$	Pull-up to $V_{ext} \leq 18V$ , $I_L \leq 3.4\text{mA}$
	$V_{satHiOd}$	90		100	% $V_{DD}$	Pull-down to 0V, $I_L \leq 3.4\text{mA}$
Output leakage in Digital Open-drain & Hi-Z modes <sup>(8)</sup>	$I_{leakpuOd}$			100	$\mu\text{A}$	Pull-up to $V_{ext} > V_{DD}$
	$I_{leakpu}$			20	$\mu\text{A}$	Pull-up to $V_{ext} = V_{DD}$
	$I_{leakpd}$			20	$\mu\text{A}$	Pull-down to 0V
Digital output Resistance	$R_{on}$	27	50	130	$\Omega$	Valid for high and low digital levels

<sup>7</sup> Typical values are representative of a temperature of 35°C and a supply voltage of 5V. Min-Max values are representative of a temperature of 160°C and a supply voltage of 4.5V.

<sup>8</sup> The digital output level is thereby defined by the external voltage and pull-up or pull-down resistor.

Electrical Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Passive Diagnostic Output Level (Broken-Wire Detection)	BV <sub>SS</sub> PD		1.2 0.5	4.0 1.6	%V <sub>DD</sub>	Broken V <sub>SS</sub> line and Pull-down to 0V, R <sub>L</sub> ≤ 25 kΩ Pull-down to 0V, R <sub>L</sub> ≤ 10 kΩ
	BV <sub>SS</sub> PU	99.5	100		%V <sub>DD</sub>	Broken V <sub>SS</sub> line and Pull-up to V <sub>ext</sub> , R <sub>L</sub> ≥ 1 kΩ
	BV <sub>DD</sub> PD		0	0.5	%V <sub>DD</sub>	Broken V <sub>DD</sub> line and Pull-down to 0V, R <sub>L</sub> ≥ 1 kΩ
	BV <sub>DD</sub> PU	92.5 97.0	98.7 99.5		%V <sub>DD</sub>	Broken V <sub>DD</sub> line and Pull-up to V <sub>ext</sub> , R <sub>L</sub> ≤ 25 kΩ Pull-up to V <sub>ext</sub> , R <sub>L</sub> ≤ 10 kΩ

*Table 12 – Output electrical specifications*

## 5.1. High-Temperature Extension Electrical Specifications

When the MLX90425 is exposed to high temperatures within the range [160, 180] °C and the supply voltage remains in the range [4.5, 5.5] V, the output pull-up voltage range shall remain within the limits of the supply voltage. This extension is only valid for the SMP packages.

Electrical Parameter	Symbol	Min	Typ	Max	Unit	Condition
External Pull-up Voltage	V <sub>ext</sub>			V <sub>DD</sub>	V	Output Pull-up voltage in open-drain NMOS mode or analog mode
Passive Diagnostic Output Level (Broken-Wire Detection)	BV <sub>DD</sub> PU	92.5			%V <sub>DD</sub>	Broken V <sub>DD</sub> line and Pull-up to V <sub>ext</sub> , R <sub>L</sub> ≤ 5 kΩ

*Table 13 – High-temperature electrical specifications*

## 6. Timing Specifications

Timing specifications are valid for temperature range [-40, 160] °C and supply voltage range [4.5, 5.5] V unless otherwise noted.

### 6.1. General Timing Specifications

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Main Clock Frequency	$F_{CK}$	22.8 -5	24	25.2 5	MHz % $F_{ck}$	Including thermal and lifetime drift
Main Clock initial tolerances	$\Delta F_{CK,0}$	-1		1	% $F_{ck}$	T=35°C, trimming resolution
Main Clock Frequency Thermal Drift	$\Delta F_{CK,T}$	-3.5		3.5	% $F_{ck}$	Relative to clock frequency at 35°C. Ageing effect not included
1MHz Clock Frequency	$F_{1M}$	0.95 -5	1	1.05 5	MHz % $F_{1M}$	Including thermal and lifetime drift
Analog Diagnostics DCT <sup>(9)</sup>	$DCT_{ANA}$		11.8	12.4	ms	Continuous acquisition mode (see 6.2), for analog and PWM.
Digital Diagnostics DCT <sup>(9)</sup>	$DCT_{DIG}$		18.7	19.7	ms	
Fail safe state duration <sup>(10)</sup>	$T_{FSS}$	5		33	ms	For digital single-event faults

Table 14 – General timing specifications

### 6.2. Continuous Acquisition Mode

In this mode, the sensor continuously acquires an angle at a fixed rate and updates its output when the information is ready. The acquisition rate is defined by the angle measurement period  $T_{angleMeas}$ . The PWM output frequency is asynchronous with the angle measurement sequence and controlled by the  $T_{FRAME}$  parameter.

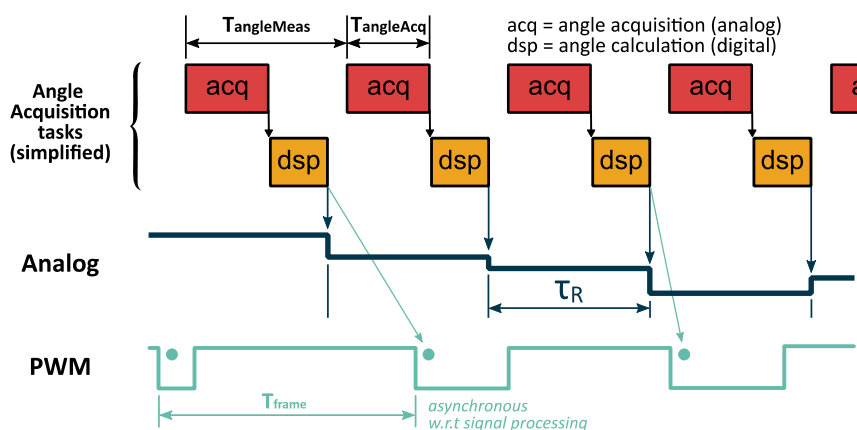


Figure 3 – Continuous Acquisition Timing Mode

<sup>9</sup> Max value includes the clock tolerances.

<sup>10</sup> Programmable parameter. Defines the time between a reset due to digital fault to the first valid data. Min. value defined by  $OUT\_DIAG\_HIZ\_TIME$  (see Table 31 in chapter 11 for details).

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Angle acquisition time	$T_{\text{angleAcq}}$		210		$\mu\text{s}$	Default factory settings
Internal Angle Measurement Period	$T_{\text{angleMeas}}$		512		$\mu\text{s}$	Default factory settings

Table 15 – Continuous acquisition timing mode

## 6.3. Timing Definitions

### 6.3.1. Start-up Time

In analog mode, the start-up time  $\tau_{\text{SU}}$  is defined by the duration between rising of the supply voltage and the output being set to the voltage level of the measured angle. During the start-up phase, the sensor output remains in a high impedance state. The output driver is enabled only when the sensor is able to transmit a valid angle.

In PWM mode, the start-up phase consists of three phases of durations  $T_{\text{stup}[1:3]}$ . The first phase ends when the sensor output leaves high impedance state and starts to drive a voltage. The end of the second phase  $T_{\text{stup}2}$  is reached when an angle is ready to be transmitted and indicated by the first synchronization edge of the PWM signal. The start-up phase is considered complete after  $T_{\text{stup}3}$  when the first angle has been transmitted, which happens one PWM period after  $T_{\text{stup}2}$ .

These definitions are illustrated in the following figure (Figure 4) where  $\tau_{\text{init}}$  represents the sensor internal initialization sequence.

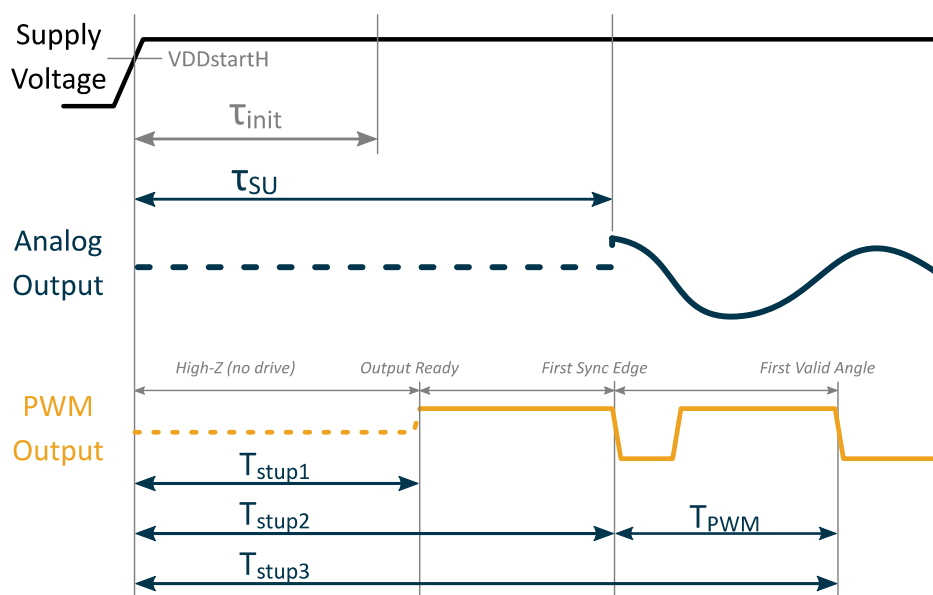


Figure 4 – Start-up time definition

### 6.3.2. Latency (average)

The sensor latency is the average lag between the movement of the detected object (magnet) and the response of the sensor output. This value is representative of the time constant of the MLX90425 when used in a regulation loop.

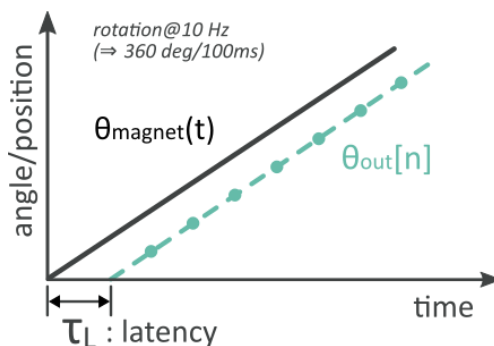


Figure 5 – Definition of latency

### 6.3.3. Step Response (worst-case)

The Step Response  $T_{wcStep}$  is defined as the maximal delay between a change of position of the magnet and the 100% settling time of the sensor output, with full angle accuracy with regards to filtering. This worst-case is happening when the movement of the magnet occurs just after a measurement sequence has begun. The Step Response consists of the sum of:

- $\delta_{mag,measSeq}$ , the delay between the magnetic step and the end of the measurement sequence
- $T_{angleMeas}$ , the internal angle measurement period
- $\delta_{measSeq,trans}$ , the delay between the end of the measurement sequence and the beginning of the transmission of the angle information
- $T_{trans}$ , the duration of the transmission of the angle information, which depends on the output protocol

The worst-case occurs when the magnetic step is just after the beginning of a measurement sequence. In other words, when  $\delta_{mag,measSeq}$  equals the length of the measurement sequence  $\tau_{measSeq}$ . This gives:

$$T_{wcStep} = \tau_{measSeq} + T_{angleMeas} + \delta_{measSeq,trans} + T_{trans}$$

In analog output mode, the angle information is immediately available after the end of the internal measurement period and the transmission delay is negligible. The last two terms of the above equation can be nulled. When using a PWM output protocol, the last two terms of the equation are, in the worst-case condition, both equal to a PWM frame duration  $T_{PWM}$ . The Figure 6 shows a practical case of a step response for both an analog and PWM output.

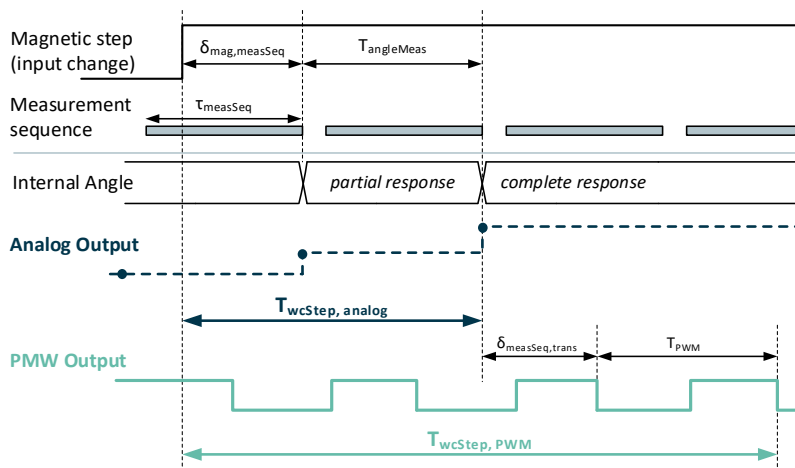


Figure 6 – Step response definition

## 6.4. Analog Output Timing Specifications

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Output refresh period <sup>(11)</sup>	$T_{\text{angleMeas}}$		512	538	$\mu\text{s}$	Default factory setting
Latency	$\tau_L$		225	237	$\mu\text{s}$	Filter 0
Step response	$T_{\text{wcStep}}$		837	879	$\mu\text{s}$	Filter 0, Filter 1, Filter 2 (see 12.4 Filtering)
			1349	1416		
		2373	2492			
Start-up time	$\tau_{\text{SU}}$		4.0	4.5	ms	
Safe start-up time <sup>(9)</sup>	$T_{\text{SafeStup}}$		16.8	17.7	ms	COLD_SAFE_STARTUP_EN = 1 (see Table 31)
Slew-rate	$S_R$	90			V/ms	$C_{\text{OUT}} = 100\text{nF}$

Table 16 – Analog output timing specifications

## 6.5. PWM Output Timing Specifications

For the parameters in below table, maximum timings correspond to minimal frequencies and vice versa.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
PWM Frequency	$F_{\text{PWM}}$	100		2000	Hz	
PWM Frequency Initial Tolerances	$\Delta F_{\text{PWM},0}$	-1		1	$\%F_{\text{PWM}}$	$T=35^\circ\text{C}$ , can be trimmed at EOL
PWM Frequency Thermal Drift	$\Delta F_{\text{PWM},T}$	-3.5		3.5	$\%F_{\text{PWM}}$	
PWM Frequency Drift	$\Delta F_{\text{PWM}}$	-5		5	$\%F_{\text{PWM}}$	Over temperature and lifetime
PWM start-up time <sup>(12)</sup>	$T_{\text{stup1}}$		4.1		ms	Default factory setting Up to output ready
	$T_{\text{stup2}}$		5.2		ms	Default factory setting Up to first sync. Edge $T_{\text{stup1}} + T_{\text{PWM}}$
	$T_{\text{stup3}}$		6.3		ms	Default factory setting Up to first data received $T_{\text{stup2}} + T_{\text{PWM}}$
PWM Safe start-up time			18.5	19.5	ms	$F_{\text{PWM}} = 1\text{kHz}$ , up to first edge. COLD_SAFE_STARTUP_EN = 1 (see Table 31)

Table 17 – PWM timing specifications

<sup>11</sup> In analog mode, the output refresh period matches the internal angle measurement period.

<sup>12</sup> Typ. value specified according to the typical PWM frequency. Max. value can be obtained by scaling with the PWM frequency drift accordingly.

## 7. Magnetic Field Specifications

Magnetic field specifications are valid for temperature range [-40, 160] °C unless otherwise noted.

### 7.1. Magnetic Field Specifications for MLX90425 Single Die

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Number of magnetic poles	$N_p$	2				
Magnetic Flux Density in Z	$B_z$			200	mT	in absolute value
Useful Magnetic Flux Density Norm	$\Delta B_z$	$10^{(13)}$	20	240	$\frac{\text{mT}}{\text{mm}}$	$\sqrt{\left(\frac{\Delta B_z}{\Delta X}\right)^2 + \left(\frac{\Delta B_z}{\Delta Y}\right)^2}$ see 12.3 for sensing mode description.
Hall Plates spacing	$\Delta X, \Delta Y$		1.70		mm	Distance between the two hall plates of a measurement axis.
Magnet Temperature Coefficient	$TC_m$	-2400		0	$\frac{\text{ppm}}{^\circ\text{C}}$	
Fieldstrength Resolution	$\Delta B_{z,\text{norm}}$	0.075	0.1	0.125	$\frac{\text{mT}}{\text{mm LSB}}$	
Field Too Low Threshold	$\Delta B_{z,\text{TH\_LOW}}$	2	3	15	$\frac{\text{mT}}{\text{mm}}$	Typ. is recommended value to be set by user (see 12.5.5)
Field Too High Threshold	$\Delta B_{z,\text{TH\_HIGH}}$	100	310	310	$\frac{\text{mT}}{\text{mm}}$	Typ. is recommended value to be set by user (see 12.5.5)

Table 18 – Magnetic specifications for standard application

The magnetic performances are listed in chapter 8.2. The Figure 7 defines under which conditions nominal or high-temperature performances apply.

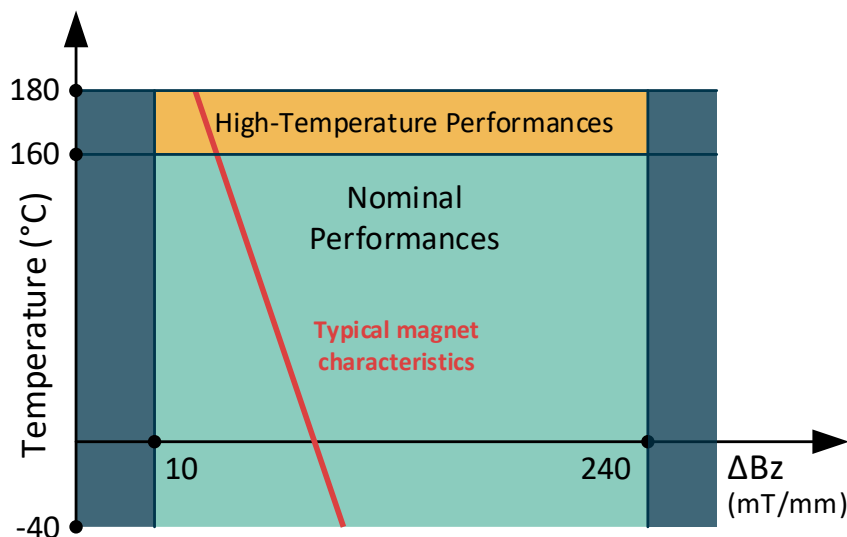


Figure 7 – Useful magnetic signal definition for single die

<sup>13</sup> Only valid under the conditions of Figure 7. Outside of the “Limited Performances” zone, the performances are further degraded due to a reduction of the signal-to-noise ratio and signal-to-offset ratio.

## 7.2. Magnetic Field Specifications for MLX90425 Stacked Dice

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Number of magnetic poles	$N_p$		2			
Magnetic Flux Density in Z	$B_z$			190	mT	in absolute value
Useful Magnetic Flux Density Norm	$\Delta B_z$	12 <sup>(14)</sup>	20	245	$\frac{\text{mT}}{\text{mm}}$	$\sqrt{\left(\frac{\Delta B_z}{\Delta X}\right)^2 + \left(\frac{\Delta B_z}{\Delta Y}\right)^2}$
Hall Plates spacing	$\Delta X, \Delta Y$		1.55		mm	Distance between the two hall plates of a measurement axis.
Magnet Temperature Coefficient	$TC_m$	-2400		0	$\frac{\text{ppm}}{^\circ\text{C}}$	
Fieldstrength Resolution	$\Delta B_{z,\text{norm}}$	0.075	0.1	0.125	$\frac{\text{mT}}{\text{mm LSB}}$	
Field Too Low Threshold	$\Delta B_{z,\text{TH\_LOW}}$	2	3	15	$\frac{\text{mT}}{\text{mm}}$	Typ. is recommended value to be set by user
Field Too High Threshold	$\Delta B_{z,\text{TH\_HIGH}}$	100	310	310	$\frac{\text{mT}}{\text{mm}}$	Typ. is recommended value to be set by user

Table 19 – Magnetic specifications for standard application

The magnetic performances are listed in chapter 8.3. The Figure 8 defines under which conditions nominal or high-temperature performances apply.

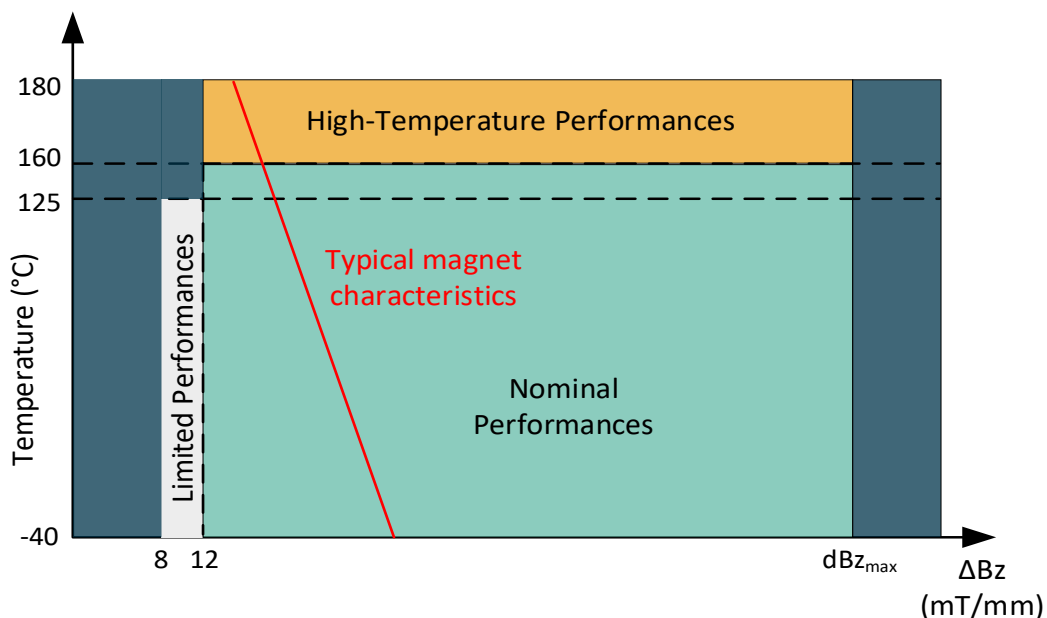


Figure 8 – Useful magnetic signal definition for stacked dice

<sup>(14)</sup> Only valid under the conditions of Figure 8. Outside of the “Limited Performances” zone, the performances are further degraded due to a reduction of the signal-to-noise ratio and signal-to-offset ratio.

## 8. Accuracy Specifications

Accuracy specifications are valid for temperature range [-40, 160] °C and supply voltage range [4.5, 5.5] V unless otherwise noted.

### 8.1. Definitions

#### 8.1.1. Intrinsic Linearity Error

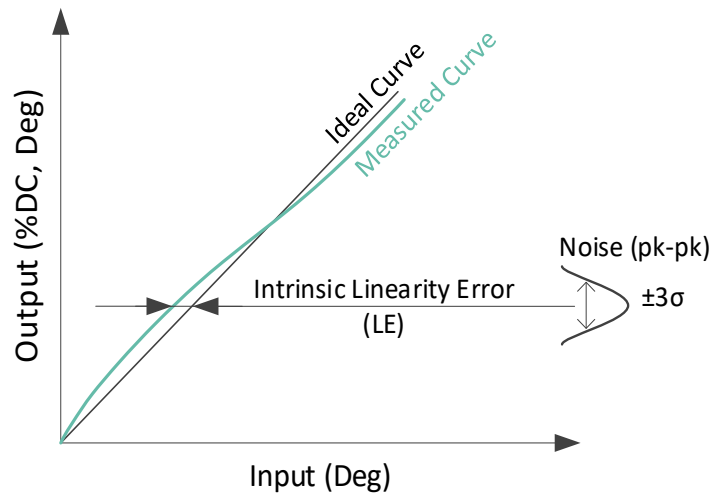


Figure 9 – Sensor accuracy definition

The illustration of Figure 9 depicts the intrinsic linearity error in new parts. The Intrinsic Linearity Error refers to the error sources of the IC (offset, sensitivity mismatch, orthogonality error) considering an ideal magnetic field. Once associated to a practical magnetic construction and its respective mechanical and magnetic tolerances, the output linearity error increases. The linearity error can be improved with the multi-point end-user calibration (see 12.2). As a consequence, this error is not the critical factor in application when it is calibrated away.

#### 8.1.2. Total Angle Drift

After calibration, the output angle of the sensor might still change due to temperature change and aging. This error is defined as the total drift  $\partial\theta_{TT}$  :

$$\partial\theta_{TT} = \max\{\theta(\theta_{IN}, T, t) - \theta(\theta_{IN}, T_{RT}, t_0)\}$$

where  $\theta_{IN}$  is the input angle,  $T$  is the temperature,  $T_{RT}$  is the room temperature, and  $t$  is the elapsed lifetime after calibration.  $t_0$  represents the start of the sensor operating life. Note that the total drift  $\partial\theta_{TT}$  is always defined with respect to the angle at room temperature. In this datasheet,  $T_{RT}$  is typically defined at 35°C unless stated otherwise. The total drift is valid for all angles along the full mechanical stroke.

## 8.2. Single die performances

Valid before EoL calibration and for all applications under nominal performances conditions described in chapter 5 and chapter 7.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Intrinsic Linearity Error	$L_{E\_ΔBz}$	-1.2		1.2	Deg.	
Noise <sup>(15)</sup>			0.40	0.50		Filter = 0, $ΔB_z ≥ 10\text{mT/mm}$
			0.19	0.24	Deg.	Filter = 0, $ΔB_z ≥ 20\text{mT/mm}$
			0.20	0.25		Filter = 2, $ΔB_z ≥ 10\text{mT/mm}$
Total Drift <sup>(16)</sup>	$∂θ_{TT\_XY}$	-0.9		0.9	Deg.	Relative to 35°C
Hysteresis <sup>(17)</sup>				0.1	Deg.	$ΔB_z ≥ 10\text{mT}$
Stray Field Immunity				0.35	Deg.	$ΔB_z ≥ 20\text{mT/mm}$
						In accordance with ISO11452-8:2015, at 30°C with stray field of 4kA/m from any direction

Table 20 – Nominal magnetic performances

### 8.2.1. High-Temperature Extension Performances

When the MLX90425 is exposed to high temperatures within the range [160, 180] °C and the supply voltage remains in the range [4.5, 5.5] V, the following magnetic performances apply.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Intrinsic Linearity Error	$L_{E\_ΔBz}$	-1.4		1.4	Deg.	
Noise <sup>(15)</sup>			0.48	0.60		Filter = 0, $ΔB_z ≥ 10\text{mT/mm}$
			0.24	0.30	Deg.	Filter = 0, $ΔB_z ≥ 20\text{mT/mm}$
			0.24	0.30		Filter = 2, $ΔB_z ≥ 10\text{mT/mm}$
Total Drift <sup>(16)</sup>	$∂θ_{TT\_XY}$	-1.1		1.1	Deg.	Relative to 35°C
Hysteresis <sup>(17)</sup>				0.1	Deg.	$ΔB_z ≥ 10\text{mT/mm}$
Stray-Field Immunity				0.35	Deg.	$ΔB_z ≥ 20\text{mT/mm}$
						In accordance with ISO11452-8:2015, at 30°C with stray field of 4kA/m from any direction

Table 21 – High-temperature magnetic performances for single die

<sup>15</sup>  $±3σ$ .

<sup>16</sup> Verification done on new and aged devices in an ideal magnetic field. An additional application-specific error arises from the non-ideal magnet and mechanical tolerance drift.

<sup>17</sup> The MLX90425 has no IMC and therefore no intrinsic source of magnetic hysteresis.

## 8.3. Stacked dice performances

### 8.3.1. Nominal Performances

Valid before EoL calibration and for all applications under nominal performances conditions (chapter 7).

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Intrinsic Linearity Error	$L_{E\_ΔBz}$	-1.3		1.3	Deg.	
Noise <sup>(15)</sup>			0.40 0.28 0.20	0.50 0.35 0.25	Deg.	Filter = 0, $ΔB_z ≥ 12mT/mm$ Filter = 0, $ΔB_z ≥ 20mT/mm$ Filter = 2, $ΔB_z ≥ 12mT/mm$
Total Drift <sup>(16)</sup>	$∂θ_{TT\_XY}$	-1.0		1.0	Deg.	Relative to 35°C
Hysteresis <sup>(17)</sup>				0.1	Deg.	$ΔB_z ≥ 12mT$
Stray Field Immunity				0.35	Deg.	$ΔB_z ≥ 20mT/mm$ In accordance with ISO11452-8:2015, at 30°C with stray field of 4kA/m from any direction

Table 22 – Nominal magnetic performances

### 8.3.2. Limited Performances

Valid before EoL calibration and for all applications under limited performances conditions (see section 7.2).

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Intrinsic Linearity Error	$L_{E\_ΔBz}$	-1.3		1.3	Deg.	
Noise <sup>(15)</sup>			0.52 0.40 0.26	0.65 0.50 0.33	Deg.	Filter = 0, $ΔB_z ≥ 8mT/mm$ Filter = 0, $ΔB_z ≥ 10mT/mm$ Filter = 2, $ΔB_z ≥ 8mT/mm$
Total Drift <sup>(16)</sup>	$∂θ_{TT\_XY}$	-1.0		1.0	Deg.	Relative to 35°C
Hysteresis <sup>(17)</sup>				0.1	Deg.	$ΔB_z ≥ 10mT$
Stray Field Immunity				0.7	Deg.	$ΔB_z ≥ 10mT/mm$ In accordance with ISO11452-8:2015, at 30°C with stray field of 4kA/m from any direction

Table 23 – Limited magnetic performances

### 8.3.3. High-Temperature Extension Performances

When the MLX90425 is exposed to high temperatures within the range [160, 180] °C and the supply voltage remains in the range [4.5, 5.5] V, the following magnetic performances apply. This extension is only valid for the SMP-3 and SMP-4 packages.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Intrinsic Linearity Error	$L_{E\_ΔBz}$	-1.3		1.3	Deg.	
Noise <sup>(15)</sup>				0.4 0.7	Deg.	Filter = 0, $ΔB_z = 20\text{mT/mm}$ , 180°C Filter = 0, $ΔB_z = 12\text{mT/mm}$ , 180°C
Total Drift <sup>(16)</sup>	$∂θ_{TT\_XY}$	-1.0		1.0	Deg.	Relative to 35°C
Hysteresis <sup>(17)</sup>				0.1	Deg.	$ΔB_z ≥ 10\text{mT/mm}$

Table 24 – High-temperature magnetic performances

## 9. Memory Specifications

Parameter	Symbol	Value	Unit	Note
ROM	ROM <sub>size</sub>	16	kB	1-bit parity check per 32-bit word (single error detection)
RAM	RAM <sub>size</sub>	512	B	1-bit parity check per 16-bit word (single error detection)
NVRAM	NVRAM <sub>size</sub>	128	B	6-bit ECC per 16-bit word (single error correction, double error detection)

Table 25 – Memory specifications

## 10. Output Protocol Description

### 10.1. Analog Output Description

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Thermal analog output Drift				0.2	%V <sub>DD</sub>	
Analog Output Resolution	R <sub>DAC</sub>		12		bit	12-bit DAC (theoretical)
		-4		+4	LSB12	INL (before EoL calibration), output between 3-97%V <sub>DD</sub>
		-1.0		1.5	LSB12	DNL
Ratiometric Error		-0.05 -0.1		0.05 0.1	%V <sub>DD</sub>	4.5V ≤ V <sub>DD</sub> ≤ 5.5V V <sub>DDUVL</sub> < V <sub>DD</sub> < V <sub>PROVO</sub>

Table 26 – Analog output accuracy

### 10.1.1. High-Temperature Extension Analog Output Description

When the MLX90425 is exposed to high-temperatures within the range [160, 180] °C and the supply voltage remains in the range [4.5, 5.5] V, the following analog output accuracy performances apply.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Thermal analog output Drift				0.25	%V <sub>DD</sub>	
Ratiometric Error		-0.1		0.1	%V <sub>DD</sub>	4.5V ≤ V <sub>DD</sub> ≤ 5.5V

Table 27 – High-temperature analog output accuracy

## 10.2. PWM Output Description

### 10.2.1. Definition

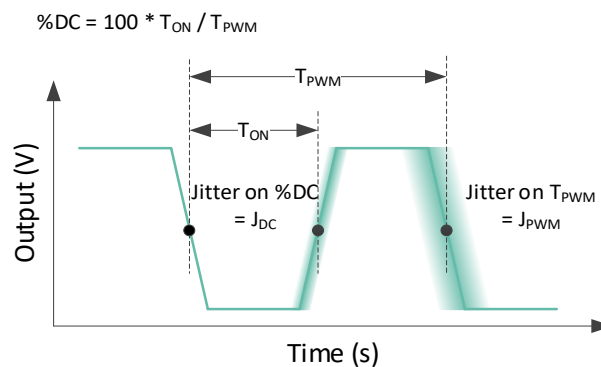


Figure 10 – PWM signal definition

Parameter	Symbol	Test Conditions
PWM period	$T_{PWM}$	Trigger level = 50% V <sub>DD</sub>
Rise time, Fall time	$t_{rise}, t_{fall}$	Between 10% and 90% of V <sub>DD</sub>
Jitter	$J_{DC}$ $J_{PWM}$	$\pm 3\sigma$ for 1000 successive acquisitions with clamped output
Duty Cycle	%DC	$100 * T_{ON} / T_{PWM}$

Table 28 – PWM signal definition

### 10.2.2. PWM performances

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
PWM period	$T_{PWM}$	0.5		10	ms	Configurable through the T_FRAME parameter
PWM Output Resolution	$R_{PWM}$		0.024		%DC/LSB12	

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
PWM %DC Jitter	J <sub>DC</sub>			0.03	%DC	C <sub>OUT</sub> = 10nF, R <sub>L</sub> = 10kΩ Push-pull, 2kHz
PWM Period Jitter	J <sub>PWM</sub>			500	ns	2kHz
PWM %DC thermal drift			0.02	0.05	%DC	C <sub>OUT</sub> = 10nF, R <sub>L</sub> = 10kΩ Push-pull, 2kHz
Rise/Fall Time PWM	T <sub>rise_fall</sub>	2.5	5.0	7.5	μs	C <sub>OUT</sub> ≤ 15nF <sup>(18)</sup> <sup>(19)</sup> Push-pull mode
Rise/Fall Active Slope PWM	S <sub>rise_fall</sub>	0.5	0.8	1.6	V/μs	C <sub>OUT</sub> ≤ 15nF <sup>(18)</sup> <sup>(19)</sup> Push-pull or open-drain mode

Table 29 – PWM signal specifications

### 10.2.3. High-Temperature Extension PWM Performances

When the MLX90425 is exposed to high-temperatures within the range [160, 180] °C and the supply voltage remains in the range [4.5, 5.5] V, the following PWM signal specifications apply.

Parameter	Symbol	Min	Typ	Max	Unit	Condition
PWM %DC thermal drift			0.05	0.1	%DC	C <sub>OUT</sub> = 10nF, R <sub>L</sub> = 10kΩ Push-pull, 2kHz

Table 30 – High-Temperature PWM Signal Specifications

## 11. End-User Programmable Items

Parameter	PSF value	Description	Default Value	# bits
<b>GENERAL CONFIGURATION</b>				
USER_ID[0:5]	98 .. 103	Reserved for end-user to program information for traceability. Not compatible with a used patch area	-	8
WARM_TRIGGER_LONG	93	Add delay for PTC entry level	0	1
MUPET_ADDRESS	97	Address to which the slave device will answer	0	2
<b>SENSOR FRONT-END</b>				
GAINMIN	2	Minimum Virtual Gain	0	6
GAINMAX	3	Maximum Virtual Gain	48	7
GAINSATURATION	4	Enable gain saturation	0	1

<sup>18</sup> The 10nF output capacitor included in the SMP-3 package needs to be considered in the 15nF limit.

<sup>19</sup> If the total load current at the output is high enough to trigger the current limit protection, then the slopes will be determined by the maximum output current drive of around 15mA (typical value).

Parameter	PSF value	Description	Default Value	# bits
SENSING_MODE	17	0: $\Delta B_z$ , angular rotary 360° stray field robust 1-3: Do not use	0	2
<b>FILTERING</b>				
FILTER	12	FIR filter bandwidth selection 0: no filter (default) 1: FIR11 2: FIR1111 3: Do not use	0	2
<b>LINEAR TRANSFER CHARACTERISTIC</b>				
4POINTS	11	Enable 4 points PWL linearization	0	1
CLAMPHIGH	19	High clamping value of angle output data	50%	12
CLAMPLOW	14	Low clamping value of angle output data	50%	12
CW	15	Magnet rotation direction	0	1
DP	10	DSP discontinuity point	0	13
LNR50	22	4-pts - Slope coefficient before reference point A	-	16
LNRAX	25	4-pts - X Coordinate for reference points A,B,C,D	-	16
LNRBX	35			
LNRXC	46			
LNRDX	58			
LNRAY	30	4-pts - Y Coordinate for reference points A,B,C,D	-	16
LNRBY	41			
LNRCY	53			
LNRDY	63			
LNRAS	32	4-pts - Slope coefficient for reference points A,B,C,D	-	16
LNRBS	43			
LNRCS	55			
LNRDS	65			

Parameter	PSF value	Description	Default Value	# bits
LNR0	24	17-pts / 16 segments - Y coordinate point [0:16]	10%	12
LNR1	26			
LNR2	31			
LNR3	34			
LNR4	37			
LNR5	42			
LNR6	45			
LNR7	48			
LNR8	54			
LNR9	57			
LNR10	60			
LNR11	64			
LNR12	67			
LNR13	70			
LNR14	75			
LNR15	77			
LNR16	79			
OUTSLOPE_COLD	81	Slope coefficient at cold of the programmable temperature-dependent offset	0	8
OUTSLOPE_HOT	82	Slope coefficient at hot of the programmable temperature-dependent offset	0	8
USEROPTION_SCALING	16	Enable output scaling 2x after linearization	0	1
WORK_RANGE	104	Working Range 17 points	0	4
WORK_RANGE_GAIN	7	Post DSP Gain Stage	16	8
<b>DIAGNOSTICS</b>				
COLD_SAFE_STARTUP_EN	50	Normal (0) or safe start-up (1) after power-on reset	0	1
DIAG_EN	40	Diagnostics global enable. <b>Do not modify!</b>	1	1
DIAG_FIELDTOOHIGHTHRES	69	Field strength limit over which a fault is reported	14	4
DIAG_FIELDTOOLOWTHRES	62	Field strength limit under which a fault is reported	0	4
DIAGDEBOUNCE_STEPDOWN	28	Diagnostic debouncing step-down time used for recovery time setting	1	2
DIAGDEBOUNCE_STEPUP	29	Diagnostic debouncing step-up time used for hold time setting	1	2
DIAGDEBOUNCE_THRESHOLD	39	Diagnostic debouncing threshold	1	3
MEMLOCK	52	Enable NVRAM write protection	0	2

Parameter	PSF value	Description	Default Value	# bits
OUT_DIAG_HIZ_TIME	90	Recovery time when a transient digital failure is detected. Timeout corresponds to DCT <sub>DIG</sub> for the default value. For recovery time of 2 DCT <sub>DIG</sub> it is recommended to program 0x14	0	5
PWM_DC_FAULT_BAND	86	PWM Upper or Lower band for analog fault reporting	0	1
PWM_DC_FAULT_VAL	85	PWM Duty Cycle in case of analog fault	0	3
PWM_DC_FIELDTOOLOW_BAND	72	PWM Upper or Lower band for analog fault reporting in case of Field Strength Too Low	-	1
PWM_DC_FIELDTOOLOW_VAL	73	PWM Duty Cycle in case of Field Strength Too Low	-	3
ROUT_LOW	91	Select output impedance for PTC communication	1	1
DAC_REPORT_MODE_ANA	21	Defines the DAC state in analog-fault report mode Refer to the Safety Manual	0	2
PWM_REPORT_MODE_ANA	89	Defines the PWM state in analog-fault report mode Refer to the Safety Manual	0	1
<b>OUTPUT CONFIGURATION</b>				
ABE_AOUT_MODE	92	Output-amplifier mode selection: 0: Analog output (12-bit DAC) 1: Digital output with open-drain NMOS 2: Digital output with open-drain PMOS 3: Digital output with Push-Pull	0	2
PROTOCOL	94	Selection of the output protocol and its corresponding timing mode: 0: Analog Output (continuous synchronous angle acquisition) 1: PWM Output (continuous asynchronous angle acquisition)	0	1
T_FRAME	84	Output PWM period PWM period = 4us * T_FRAME	250	12
PWM_POL	88	Invert the PWM polarity	0	1
ABE_CURR_LIMITER	105	Enables slow PWM slopes. Do not modify!	0	1

Table 31 – MLX90425 end-user programmable items table

Performances described in this document are only achieved by adequate programming of the device. To ensure desired functionality, Melexis recommends to follow its programming guide and to contact its technical or application service.

## 12. Description of End-User Programmable Items

### 12.1. Output modes and protocols

The MLX90425 offers an analog output mode and a digital output mode using the PWM protocol.

#### 12.1.1. Output Modes

The parameter ABE\_OUT\_MODE defines the output stage mode (outside of fail-safe state) in application.

ABE_OUT_MODE	Description	Comments
0	Analog output (12-bit DAC)	Default
1	Digital output with open-drain NMOS	Requires a pull-up resistor on the output
2	Digital output with open-drain PMOS	Requires a pull-down resistor on the output
3	Digital output with push-pull	

Table 32 – Output mode selection

#### 12.1.2. Protocol

The parameter PROTOCOL defined the measurement timings mode and the corresponding output protocol.

PROTOCOL	Description
0	Continuous synchronous angle acquisition, analog output (DAC)
1	Continuous asynchronous angle acquisition, PWM

Table 33 – Protocol selection

#### 12.1.3. PWM Protocol

If a digital output mode is selected, the output signal is a Pulse Width Modulation (PWM) digital signal.

The PWM polarity is selected by the PWM\_POL parameter:

- PWM\_POL = 0 for a low level at 100%
- PWM\_POL = 1 for a high level at 100%

The PWM frequency is selected in the range [100, 2000] Hz by the  $T\_FRAME$  parameter (12-bit value), defining the period time in the range [0.5, 10] ms. Minimum allowed value for  $T\_FRAME$  is therefore 125 (0x7D).

$$T_{PWM} = \frac{4}{10^6} \times T\_FRAME$$

PWM timings specifications in the scope of the MLX90425 can be found in section 6.5 while PWM signal characteristics such the rise time, fall times, jitter, can be found in section 10.2.

## 12.2. Output Transfer Characteristic

There are 2 different possibilities to define the transfer function (LNR) as specified in Table 34.

- With 4 arbitrary points (defined by X and Y coordinates) and 5 slopes
- With 17 equidistant points for which only the Y coordinates are defined

Output Transfer Characteristic	4POINTS
4 Arbitrary Points	1
17 Equidistant Points	0

Table 34 – Output transfer characteristic selection table

### 12.2.1. Clockwise Parameter

The CW parameter defines the magnet rotation direction.

Rotation Direction	CW
Clockwise	1
Counter Clockwise	0

Table 35 – Magnet rotation selection table

Counter clockwise is the defined by

- the 1-4-5-8 pin order direction for the SOIC-8 package
- the 1-2-3 pin order direction for the SMP-3 package
- the 1-8-9-16 pin order direction for the TSSOP-16\_EP package
- the 1-2-3-4 pin order direction for the SMP-4 package

Clockwise if defined by the reverse pin order. Refer to the package drawings in chapter 17.

### 12.2.2. Discontinuity Point (or Zero Degree Point)

The Discontinuity Point defines the 0° point on the circle. The discontinuity point places the new origin at any location of the trigonometric circle. The DP is used as reference for all angular measurements.

$$\text{New Angle} = \text{Angle} - \text{DP}$$

The DP parameter is encoded using a signed 13-bit format (two's complement). The new angle and the input angle are expressed in LSB12.

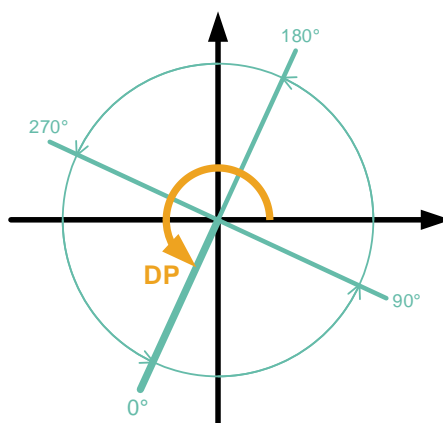


Figure 11 – Discontinuity point positioning (for CW=0)

### 12.2.3. 4-Pts LNR Parameters

The LNR parameters, together with the clamping values, define the transfer function between the internal digital representation of the angle and the output signal.

The shape of the MLX90425 four points transfer function from the internal angle to the output value is described in the following figure (Figure 12). Seven segments can be programmed using points and slopes. The segments beyond the clamping levels are necessarily flat.

Two to six calibration points are available, reducing the overall non-linearity of the IC by almost an order of magnitude each time. Three or more calibration point will be preferred by customers looking for excellent non-linearity figures. Two-point calibrations will be preferred by customers looking for a cheaper calibration set-up and shorter calibration time.

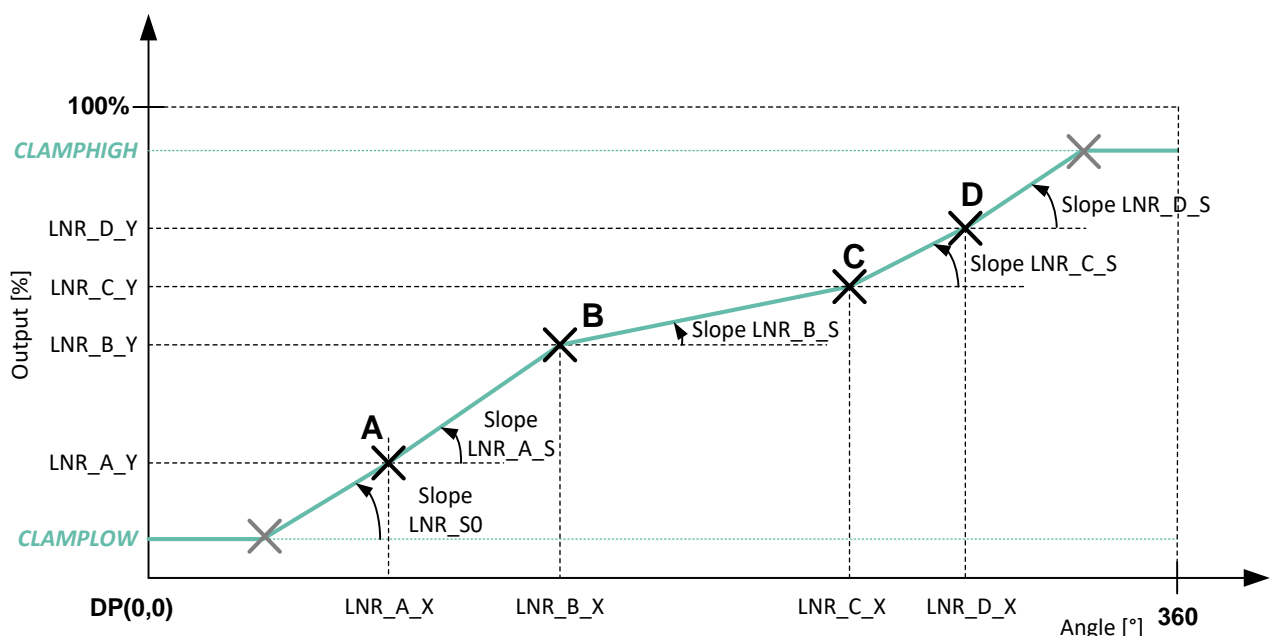


Figure 12 – 4pts linearization parameters description

### 12.2.4. 17-pts LNR Parameters

The LNR parameters, together with the clamping values, define the transfer function between the internal digital representation of the angle and the output signal.

The shape of the MLX90425 seventeen points transfer function from the internal angle to the output value is described in the Figure 13. In the 17-pts mode, the output transfer characteristic is Piecewise Linear (PWL).

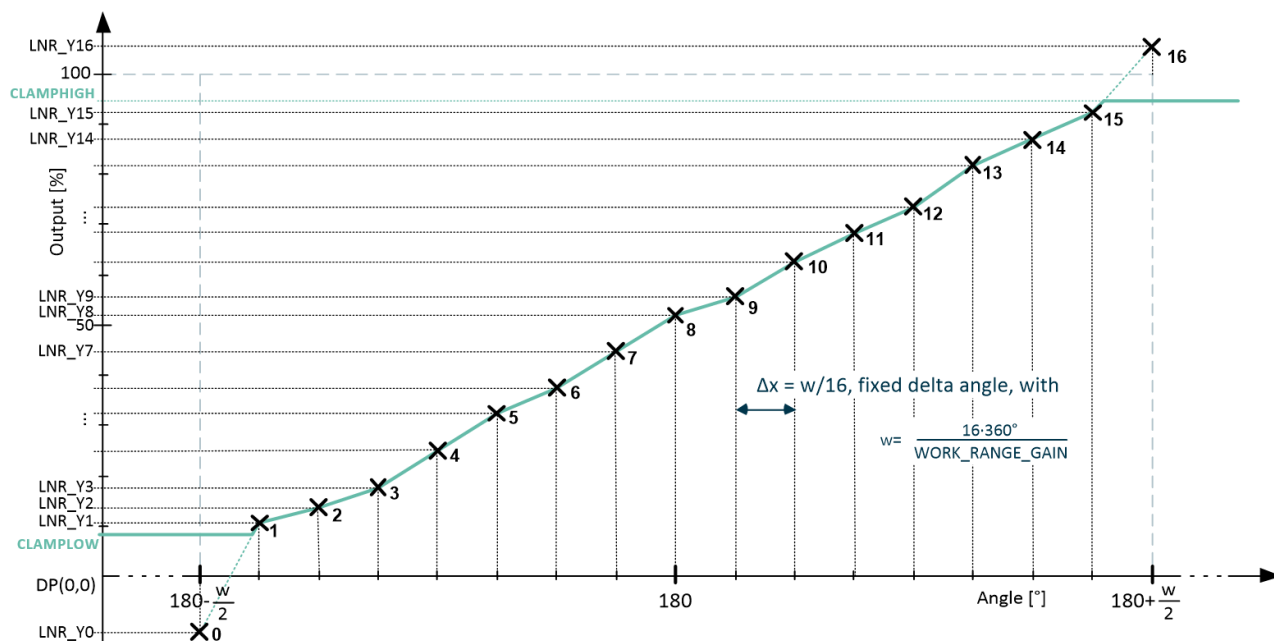


Figure 13 – 17-pts linearization parameters description

All the Y-coordinates can be programmed from -50% up to +150% to allow clamping in the middle of one segment (like on the figure), but the output value is limited to CLAMPLOW and CLAMPHIGH values. Between two consecutive points, the output characteristic is interpolated.

### 12.2.5. WORK\_RANGE Parameter for Angle Range Selection

The parameter WORK\_RANGE determines the input range on which the 16 segments are uniformly spread. This parameter is provided for compatibility with former versions of Melexis Triaxis® sensors.

For full featured working range selection, see section 12.2.6. For WORK\_RANGE parameter, following table applies.

WORK_RANGE	Range	$\Delta x$ 17-pts	WORK_RANGE	Range	$\Delta x$ 17-pts
0	360.0°	22.5°	8	180.0°	11.3°
1	320.0°	20.0°	9	144.0°	9.0°
2	288.0°	18.0°	10	120.0°	7.5°
3	261.8°	16.4°	11	102.9°	6.4°
4	240.0°	15.0°	12	90.0°	5.6°
5	221.5°	13.8°	13	80.0°	5.0°
6	205.7°	12.9°	14	72.0°	4.5°
7	192.0°	12.0°	15	65.5°	4.1°

Table 36 – Work range for 360° periodicity

Outside of the selected range, the output will remain at clamping levels.

### 12.2.6. WORK\_RANGE\_GAIN Parameter for Angle Range Selection

Alternatively, the range for the angle can be selected using the WORK\_RANGE\_GAIN parameter, which applies a fixed gain to the transfer characteristics. WORK\_RANGE\_GAIN is coded on 8 bits where the 4 MSB defines the integer part and the 4 LSB the fractional part (in power of twos). Therefore, the following equation applies to define the angle range  $w$ :

$$w = \frac{16 * 360}{WORK\_RANGE\_GAIN}$$

Both minimal and maximal angles are then defined by:

$$\theta_{min} = \frac{360 - w}{2} ; \theta_{max} = \frac{360 + w}{2}$$

where  $\theta_{min}$  corresponds to the angle yielding 0% output and  $\theta_{max}$  the angle giving a 100% output.

Using WORK\_RANGE\_GAIN parameter, the anchor point is kept at 180 and the range is symmetrically set around this value. It creates a zoom-in of the angle around this point.

The following table gives some values as examples.

WORK_RANGE_GAIN	Factor	Range (w)	$\theta_{min}$	$\theta_{max}$	$\Delta x$ 17-pts
0x10	1	360°	0°	360°	22.5°
0x20	2	180°	90°	270°	11.3°
0x40	4	90°	135°	225°	5.6°
0xFF	15.94	22.6°	168.7°	191.3°	1.41°

*Table 37 – Working range defined by WORK\_RANGE\_GAIN parameter*

Outside of the working range, the output will remain at clamping levels.

### 12.2.7. Thermal OUTSLOPE Offset Correction

Two parameters, OUTSLOPE\_HOT and OUTSLOPE\_COLD, are used to add a temperature dependent offset. In the MLX90425, this offset is applied to the angle just before the clamping function.

The offset shift is computed using the device internal linearized temperature as depicted in the figure below (Figure 14).

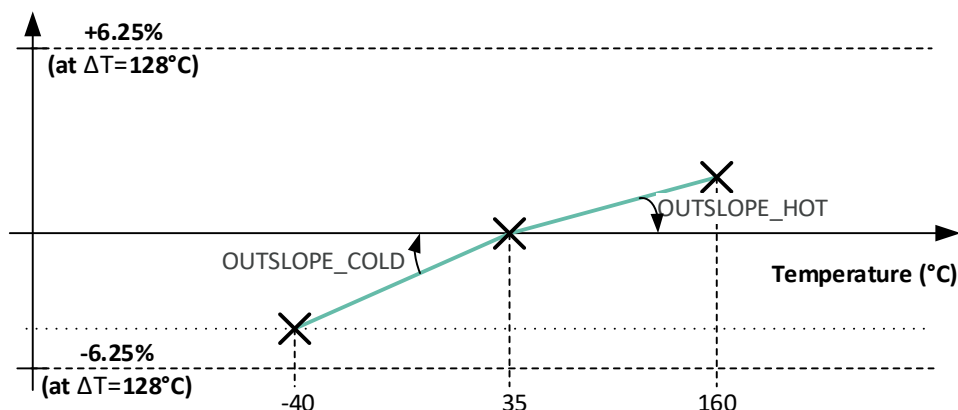


Figure 14 – Temperature compensated offset

The thermal offset can be added or subtracted to the output, before the clamping. The span of this offset is  $\pm 6.25\%$  of the full output scale for a temperature difference of  $128^{\circ}\text{C}$ . Two thermal coefficients are defined depending on whether the linearized temperature is below (`OUTSLOPE_COLD`) or above (`OUTSLOPE_HOT`) the  $35^{\circ}\text{C}$  anchor point.

If the device internal temperature is higher than  $35^{\circ}\text{C}$  then:

$$\text{Compensated Angle} = \text{Angle} - \Delta T \cdot \frac{\text{OUTSLOPE\_HOT}}{64}$$

If the device internal temperature is lower than  $35^{\circ}\text{C}$  then:

$$\text{Compensated Angle} = \text{Angle} - \Delta T \cdot \frac{\text{OUTSLOPE\_COLD}}{64}$$

Each of the two thermal coefficients is encoded using an 8-bit two's complement signed format. The thermally compensated angle and the input angle are expressed in LSB12, while the linearized temperature difference  $\Delta T$  is expressed in  $^{\circ}\text{C}$ .

### 12.2.8. Clamping Parameters

The clamping levels are two independent values to limit the output voltage range in normal operation. The `CLAMPLOW` parameter adjusts the minimum output level. The `CLAMPHIGH` parameter sets the maximum output level. Both parameters have 12 bits of adjustment and are available for all LNR modes. The values are encoded in fractional code, from 0% to 100%

## 12.3. Sensor Front-End

The `SENSING_MODE` parameter defines which sensing mode and fields are used to calculate the angle. The different possibilities are described in the tables below. This 2-bit value selects the first (B1) and second (B2) field components according to the Table 39 content.

Parameter	Value
SENSING_MODE	[0:2]
GAINMIN	[0:47]
GAINMAX <sup>(20)</sup>	[0:48]
GAINSATURATION	[0:1]

Table 38 – Sensing Mode and Front-End Configuration

SENSING_MODE	B1	B2	Motion
0	$\frac{\Delta B_z}{\Delta X}$	$\frac{\Delta B_z}{\Delta Y}$	$\Delta B_z$ , angular rotary 360° stray field robust
1, 2, 3	N/A	N/A	Do not use

Table 39 – Sensing mode description

GAINMIN and GAINMAX define the thresholds of the gain monitor diagnostic. Whenever the virtual gain is strictly outside of these limits, the diagnostic reports a fault. When GAINMIN = 0 or GAINMAX > 47, the corresponding fault reporting is disabled.

If GAINSATURATION is set, then the virtual gain is held between GAINMIN and GAINMAX values. The saturation of the gain applies before the diagnostic is checked. Therefore, the gain monitor diagnostic can be considered inactive.

## 12.4. Filtering

The MLX90425 features 2 low-pass FIR filter modes controlled with FILTER = 1...2. FILTER = 0 corresponds to no filtering. The transfer function is described by:

$$y_n = \frac{1}{\sum_{i=0}^j a_i} \sum_{i=0}^j a_i x_{n-i}$$

This filter characteristic is given in the Table 40.

FILTER	0	1	2
Type	Disable	Finite Impulse Response (FIR)	
Coefficients $a_i$	1	11	1111
Title	No filter	ExtraLight	Light
DSP cycles (j= nb of taps)	1	2	4
Efficiency RMS (dB)	0	3.0	6.0

Table 40 – FIR filter characteristics

<sup>20</sup> A value of 48 (0x30) or above disables the diagnostic.

## 12.5. Programmable Diagnostics Settings

### 12.5.1. Diagnostics Global Enable

DIAG\_EN should be kept to its default value (1) to retain all functional safety abilities of the MLX90425. This feature shall not be disabled.

### 12.5.2. Diagnostic Debouncer

A debouncing algorithm is available for analog diagnostic reporting. Enabling this debouncer will increase the FHTI of the device. Therefore, Melexis recommends keeping the debouncing of analog faults off by not modifying below described values. The factory default settings mentioned in chapter 11 should be used.

Parameter	Description
DIAGDEBOUNCE_STEPDOWN	Decrement values for debouncer counter. The counter is decremented once per evaluation cycle when no analog fault is detected.
DIAGDEBOUNCE_STEPUP	Increment value for debouncer counter. The counter is incremented once per evaluation cycle when an analog fault is detected.
DIAGDEBOUNCE_THRESH	Threshold for debouncer counter to enter diagnostic mode. When set to 0, debouncing is off and analog faults are reported immediately after detection.

Table 41 – Diagnostic debouncing parameters

Once an analog monitor detects an error, it takes control of the debouncing counter. This counter will be incremented by DIAGDEBOUNCE\_STEPUP value each time this specific monitor is evaluated and the error is still present. When the debouncing counter reaches the value defined by DIAGDEBOUNCE\_THRESH, an error is reported on the error channel, and the debouncing counter stays clamped to this DEBOUNCE\_THRESH value (see section 12.5.6 for PWM error reporting). Once the error disappears, each time its monitor is evaluated, the debouncing counter is decremented by DIAGDEBOUNCE\_STEPDOWN value. When the debouncing counter reaches zero, the error disappears from the reporting channel and the debouncing counter is released. To implement proper reporting times, one should refer to the FHTI, see chapter 13.3. The reporting and recovery time are defined in the table below (valid for DIAGDEBOUNCE\_THRESH > 0).

Parameter	Min	Max
Reporting Time	$DCT \cdot \left( \left\lceil \frac{THRESH}{STEPUP} \right\rceil - 1 \right)$	$DCT \cdot \left( \left\lceil \frac{THRESH}{STEPUP} \right\rceil \right)$
Recovery Time	$DCT \cdot \left( \left\lceil \frac{THRESH}{STEPDOWN} \right\rceil \right)$	$DCT \cdot \left( \left\lceil \frac{THRESH}{STEPDOWN} \right\rceil + 1 \right)$
	$\left\lceil \frac{x}{y} \right\rceil$	is the ceiling function of x divided by y

Table 42 – Diagnostic reporting and recovery times

### 12.5.3. Over/Under Temperature Diagnostic

DIAG\_TEMP\_THR\_HIGH defines the threshold for over temperature detection and is compared to the linearized value of the temperature sensor  $T_{LIN}$ . DIAG\_TEMP\_THR\_LOW defines the threshold for under temperature detection and is compared to the linearized value of the temperature sensor  $T_{LIN}$ .

One can get the physical temperature  $T_{PHY}$  of the die from  $T_{LIN}$  using following formula

$$T_{PHY}[^{\circ}C] = \frac{T_{LIN}}{8} - 73.15$$

Unlike  $T_{LIN}$ , DIAG\_TEMP\_THR\_LOW and DIAG\_TEMP\_THR\_HIGH are encoded using 8-bit unsigned values. Therefore, a factor of 16 must be considered when comparing either threshold to  $T_{LIN}$ .

$$DIAG\_TEMP\_THR\_(LOW/HIGH) = \frac{T_{LIN}}{16}$$

The following table summarizes the characteristics of the linearized temperature sensor and the encoding of the temperature monitor thresholds.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
$T_{LIN}$ resolution	Res <sub>TLIN</sub>	-	0.125	-	°C	12-bit range
$T_{LIN}$ refresh rate	F <sub>S,TLIN</sub>	-	200	-	Hz	
$T_{LIN}$ linearity error	T <sub>LinErr</sub>	-8	-	8	°C	from -40 to 160°C
$T_{LIN}$ linearity error	T <sub>LinErr</sub>	-2	-	6	°C	from 35 to 125°C
Low temperature threshold	DIAG_TEMP_THR_LOW	-	8	-	LSB8	Fixed value, corresponds to -57°C
High temperature threshold	DIAG_TEMP_THR_HIGH	-	136	-	LSB8	Fixed value, corresponds to 199°C
High/low temperature threshold resolution	Res <sub>Tthr</sub>	-	2	-	°C	8-bit range

Table 43 – Linearized temperature sensor characteristics

### 12.5.4. High-Temperature Extension Over-Temperature Diagnostic

When operating at a junction temperature up to 175°C, the MLX90425 retains all its diagnostic features. There's no risk of false-positive. Above this temperature, the overheating monitor enters its detection range. The default configuration of this monitor reports a typical junction temperature of 199°C. Due to temperature sensor tolerances and noise at high temperatures, Melexis recommends to increase the safety margin above 15°C. Consequently, if the sensor operates up to 190°C of junction temperature, Melexis cannot guarantee that the overheating monitor will not report an error and recommends to adapt the overheating monitor threshold to 207°C. This can be done by reprogramming a custom device configuration (patch) shown in Table 14 below. Contact a Melexis representative for further information.

Parameter	Patch Content
PATCH2_ADDRESS	0x396A
PATCH2_I	0x008C

Table 44 – High-temperature extension patch to prevent false-positive on overheating monitor

### 12.5.5. Field Strength and Field Monitoring Diagnostics

Field Strength is compensated over the operating temperature range and represents a reliable image of the differential field intensity generated by the magnet. The lower and upper limits for this diagnostic are set with the parameters described in the following table. Both parameters are encoded on four bits. They start at the respective “min” value and increase by “step” with each additional LSB.

Parameter	Min	Max	Step	Unit
DIAG_FIELDTOOLOWTHRES	0	15	1	mT/mm
DIAG_FIELDTOOHIGHTHRES <sup>(21)</sup>	100	310	15	mT/mm

*Table 45 – Field Monitor Diagnostic limits*

### 12.5.6. Analog Mode Diagnostic Reporting

When in analog mode, a digital fault is reported by configuring the OUT pin in high-impedance. Conversely, an analog fault is reported by pulling the OUT pin to the  $V_{satD\_lopp}$  low level (refer to Table 12).

This behavior is only valid for the factory default settings. Other reporting behaviors and further information on the safe-states are available in the safety manual of the MLX90425.

### 12.5.7. PWM Mode Diagnostic Reporting

When in PWM mode, a digital fault is reported by configuring the OUT pin in high-impedance.

When reporting an analog fault, the parameter PWM\_DC\_FAULT\_BAND and PWM\_DC\_FAULT\_VAL can be used to specify the 12-bit output level. The parameter PWM\_DC\_FAULT\_BAND is used to define the BAND within which the output level is set.

PWM_DC_FAULT_BAND	Description
0	The Low band [0:CLAMPLOW] is selected
1	The High band [CLAMPHIGH:4095] is selected

*Table 46 – Output level band selection in case of an analog fault*

The parameter PWM\_DC\_FAULT\_VAL selects a value in the specified band

$$\text{Low band output level} = \text{PWM\_DC\_FAULT\_VAL} \cdot \left( \frac{\text{CLAMPLOW}}{8} \right)$$

$$\text{High band output level} = 4095 - \text{PWM\_DC\_FAULT\_VAL} \cdot \left( \frac{4095 - \text{CLAMPHIGH}}{8} \right)$$

Correspondingly, the parameters PWM\_DC\_FIELDTOOLOW\_BAND and PWM\_DC\_FIELDTOOLOW\_VAL can be used to specify the 12-bit output level in case of a field strength too low event.

This reporting behavior is only valid for the factory default settings, with the exception of the aforementioned parameters in this section. Other reporting behaviors and further information on the safe-states are available in the safety manual of the MLX90425.

<sup>21</sup> When this parameter is set the maximum value of 15 (0xF), the FIELD\_TOO\_HIGH diagnostic is disabled (see Table 18).

## 13. Functional Safety

### 13.1. Safety Manual

The safety manual, available upon request, contains the necessary information to integrate the MLX90425 component in a safety related item, as a Safety Element Out-of-Context (SEooC).

In particular, it includes:

- The description of the Product Development lifecycle tailored for the Safety Element.
- An extract of the Technical Safety concept.
- The description of Assumptions-of-Use (AoU) of the element with respect to its intended use, including:
  - assumptions on the device safe state;
  - assumptions on fault tolerant time interval and multiple-point faults detection interval;
  - assumptions on the context, including its external interfaces;
- The description of safety analysis results (at the device level, to be used for the system integration), HW architectural metrics and description of dependent failures initiators.
- The description and the result of the functional safety assessment process; list of confirmation measures and description of the independency level.

### 13.2. Safety Mechanisms

The MLX90425 provides numerous self-diagnostic features (safety mechanisms). Those features increase the robustness of the IC functionality either by preventing the IC from providing an erroneous output signal or by reporting the failure.

Legend
● High coverage
○ Medium coverage
ANA: Analog hardware failure reporting mode, described in the safety manual
High-Z: A special failure reporting mode where the output is set in high-impedance mode (no HW fail-safe mode/timeout, no SW safe start-up)
DIG: Digital hardware failure reporting mode, described in the safety manual
At Start-up: A HW fault present at time zero is detected before the first frame is transmitted.
DIAG_EN: This safety mechanism can be disabled by setting DIAG_EN = 0 (see chapter 12.5.1). This option should not be used in application mode!

*Table 47 – Self diagnostic legend*

Category and safety mechanism name	Front-end	ADC	DSP	Back-end	Support. Func.	Module & Package	Reporting mode	At start-up	DIAG EN
<b>Signal-conditioning Diagnostic</b>	●	●	○			●			
Magnetic Signal Conditioning Voltage Test Pattern	●	○	○				ANA	NO	●
Magnetic Signal Conditioning Rough Offset Clipping check	●		○				ANA	NO	●
Magnetic Signal Conditioning Gain Monitor & Clamping	●		○			●	ANA	YES	●
Mag. Sig. Cond. Failure Control by the Chopping Technique	●						n/a	n/a	
A/D Converter Test Pattern		●					ANA	NO	●
ADC Conversion errors & Overflow Errors		●					ANA	YES	●
ADC Common Mode Monitor		●					n/a	YES	
Flux Monitor (Rotary mode)	●	○				●	ANA	NO	●

Category and safety mechanism name	Front-end	ADC	DSP	Back-end	Support. Func.	Module & Package	Reporting mode	At start-up	DIAG EN
<b>Digital-circuit Diagnostic</b>		●	●		○				
RAM Parity, 1-bit per 16-bit word, ISO D.2.5.2			●				DIG	YES	
ROM Parity, 1-bit per 32-bit word, ISO D.2.5.2			●				DIG	YES	
NVRAM 16-bit signature (run-time) ISO D.2.4.3, by means of SW CRC-CCITT16			●				DIG	NO	
NVRAM Double Error Detection ECC ISO D.2.4.1			●				DIG	YES	
Logical Monitoring of Program Sequence ISO D.2.9.3 via Watchdog "IWD" (CPU clock) ISO D.2.9.2			●		○		DIG	NO	●
Watchdog "AWD" (separate clock) ISO D2.9.1			●		○		DIG	YES	
CPU Errors "Invalid Address", "Wrong opcode"			●		○		DIG	YES	
ADC Interface Checksum		●					DIG	NO	●
ADC Internal Errors		○					DIG	YES	
DSP Test Pattern (atan2)			●		○		DIG	NO	●
Critical Ports Monitoring			●				DIG	NO	●
ADC Data Adder Test - Range Check and Buffer alignment		○					DIG	YES	●
ADC Data Adder Error		○					DIG	YES	
DSP Overflow	○	○	●				ANA	NO	●

Category and safety mechanism name	Front-end	ADC	DSP	Back-end	Support. Func.	Module & Package	Reporting mode	At start-up	DIAG EN
<b>System-level Diagnostic</b>									
Supply Voltage Monitors (all supply domains except VDD_OV & POR)					●	●	ANA	YES	●
External Supply Over-voltage Monitor					●	●	High-Z	YES	
Digital Supply Under-voltage Monitor (Power-on Reset)					●	●	High-Z	YES	
Overheating Monitor	○	○	○	○	○	●	ANA	YES	●
<b>Warning/Reporting Mechanisms</b>									
HW Error Controller			●	●	●		DIG	n/a	
HW Fail-safe mode with timeout			●	●	●		High-Z	n/a	
Analog-type Error management	●	●			●		ANA	n/a	
Safe start-up mode			●		●		DIG	n/a	
<b>Mechanisms executed at start-up only</b>									
RAM March-C HW Test at start-up			●		●		DIG	YES	

Table 48 – MLX90425 list of self-diagnostics with characteristics

### 13.3. Fault Handling Time Interval

The Fault handling Time Interval (FHTI) is defined as the time interval between the occurrence of a fault causing a malfunction in the MLX90425 and the end of the last frame preceding the transition into the defined fail-safe state.

The following table provides the worst-case FHTI for both an analog fault and a digital fault in MLX90425.

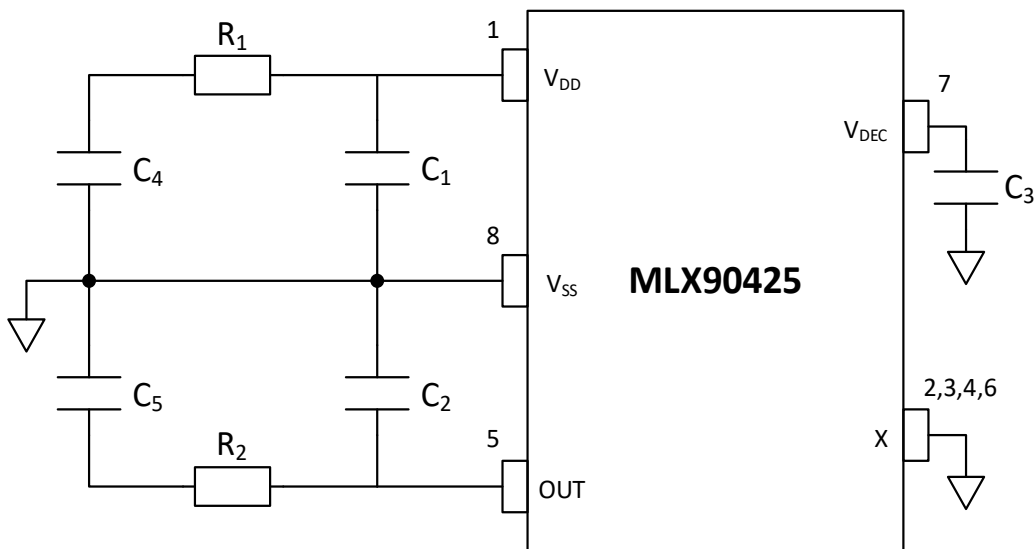
Case	FHTI	Comment
Analog Fault	$DCT_{ANA} + 2 T_{frame}$	Refer to section 6.1 for the $DCT_{ANA}$ value In analog mode, $T_{frame} = 0ms$ In PWM mode, $T_{frame} = T_{PWM}$ (see sections 10.2.2 and 0)
Digital Fault	$DCT_{DIG}$	Refer to section 6.1 for the $DCT_{DIG}$ value

*Table 49 – Worst-case FHTI*

The FHTI values provided here are valid only for the default factory settings.

## 14. Recommended Application Diagrams

### 14.1. Wiring with the MLX90425 in SOIC-8 Package



*Figure 15 – Recommended wiring for the MLX90425 in SOIC-8 package*

Component	Min	Typ.	Max	Remark
C <sub>1</sub>	100nF	220 nF	-	
C <sub>2</sub> (C <sub>L</sub> )	10 nF	10 nF	100 nF	Analog output <sup>22</sup>
	4.7 nF	10 nF	22 nF	PWM output
C <sub>3</sub>	100nF	100 nF	220 nF	
C <sub>4</sub>	-	-	1 nF	
C <sub>5</sub>	-	-	1 nF	Optional, for improved EMC robustness
R <sub>1</sub>	-	-	10 Ω	
R <sub>2</sub>	-	-	-	

Table 50 – Recommended values for the MLX90425 in SOIC-8 Package

For best EMC performance, C<sub>1</sub>, C<sub>2</sub> and C<sub>3</sub> with typical values need to be placed as close as possible to the IC. To further improve EMC robustness, a 1nF capacitor can be placed close to the connector (C<sub>4</sub>, C<sub>5</sub>) and a 10 Ω resistor added in series with the supply line (R<sub>1</sub>).

### 14.2. Wiring with the MLX90425 in SMP-3 Package (built-in capacitors)

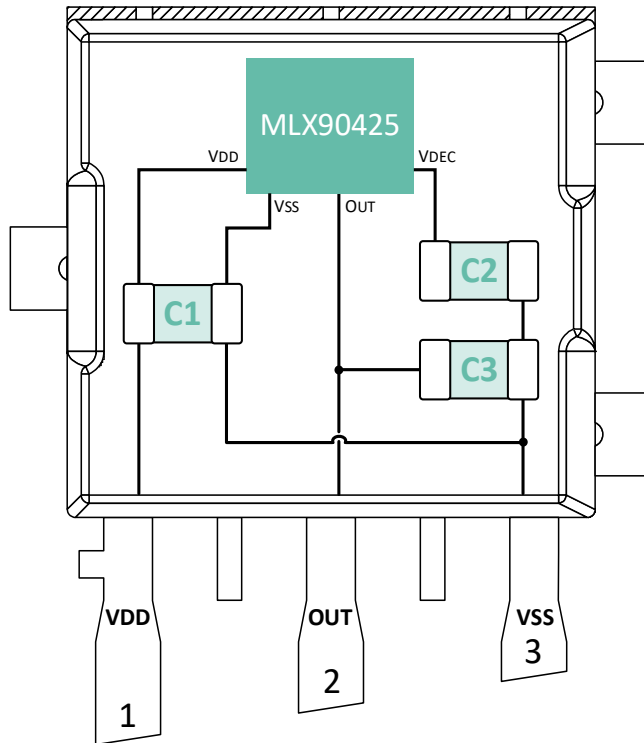


Figure 16 – Internal wiring of the MLX90425 in SMP-3

Component	Value	Remark
C1	220nF	Supply capacitor
C2	100nF	Decoupling capacitor
C3	10nF	Output capacitor

<sup>22</sup> Use 100nF for stringent EMC requirements

### 14.3. Wiring with the MLX90425 in TSSOP-16\_EP Package

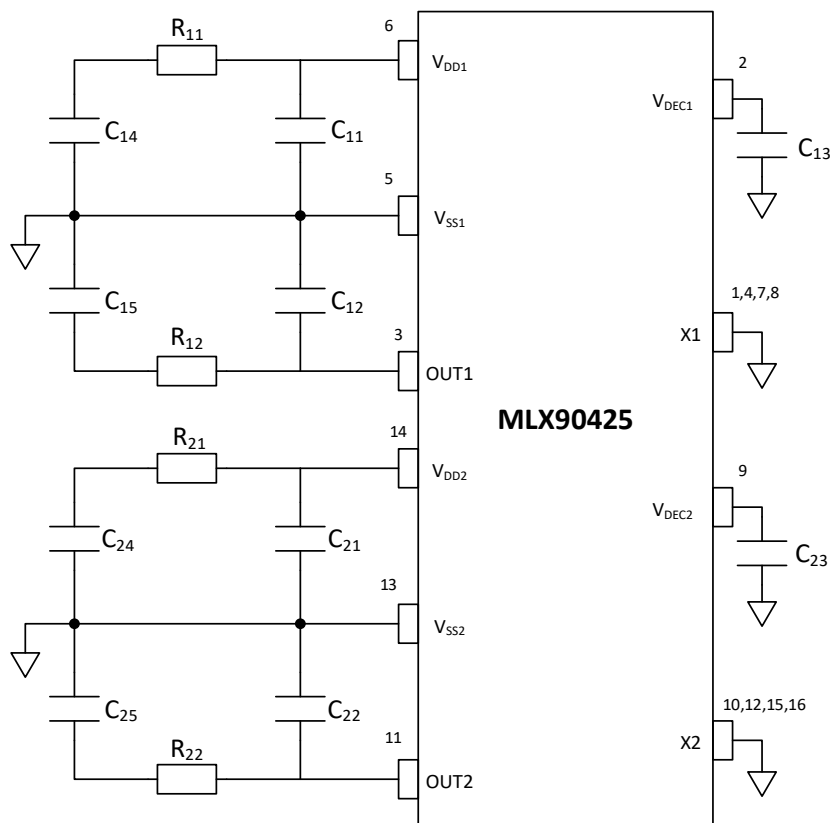


Figure 17 – Recommended wiring for the MLX90425 in TSSOP-16\_EP package (stacked-dice)

Component	Min	Typ.	Max	Remark	
C <sub>x1</sub>	100nF	220 nF	-		
C <sub>x2</sub> (C <sub>L</sub> )	10nF	10nF	100nF	Analog <sup>23</sup>	ABE_AOUT_MODE=0
	4.7nF	10nF	22nF	PWM	ABE_AOUT_MODE=1,2,3
C <sub>x3</sub>	100 nF	100 nF	220 nF		
C <sub>x4</sub>	-	-	1 nF		
C <sub>x5</sub>	-	-	1 nF	Optional, for improved	
R <sub>x1</sub>	-	-	10 Ω	EMC robustness	
R <sub>x2</sub>	-	-	-		

Table 52 – Recommended values for the MLX90425 in TSSOP-16\_EP Package

For best EMC performance, C<sub>x1</sub>, C<sub>x2</sub> and C<sub>x3</sub> with typical values need to be placed as close as possible to the IC. To further improve EMC robustness, a 1nF capacitor can be placed close to the connector (C<sub>x4</sub>, C<sub>x5</sub>) and a 10 Ohm resistor added in series with the supply line (R<sub>x1</sub>).

<sup>23</sup> Use 100nF for stringent EMC requirements

### 14.4. Wiring with the MLX90425 in SMP-4 Package (built-in capacitors)

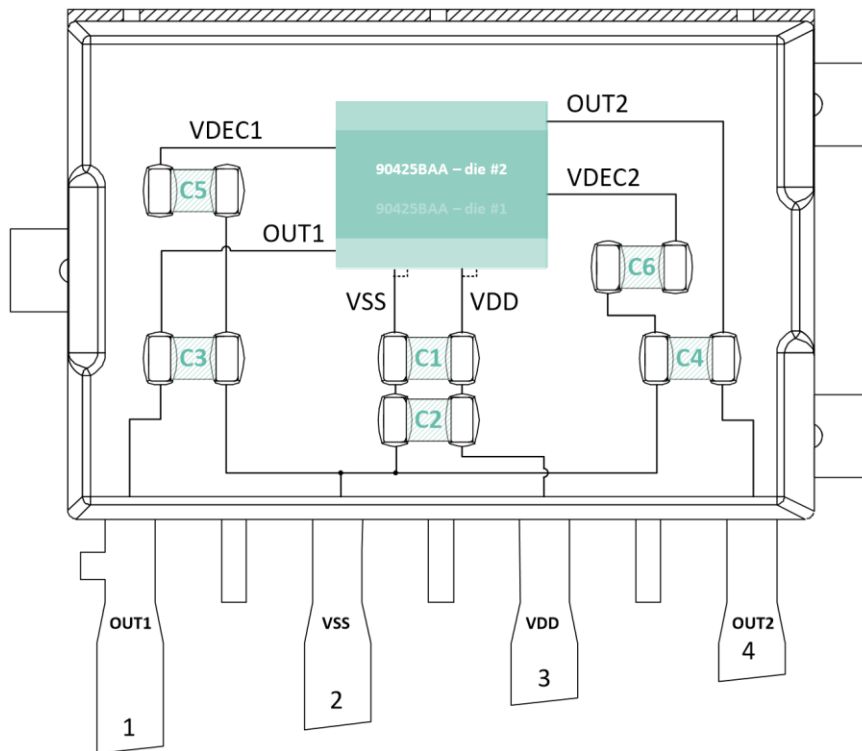


Figure 18 – Internal wiring of the MLX90425 in SMP-4

Component	Value	Remark
C1	220nF	Supply capacitor
C2		
C3	10nF	Output capacitor
C4		
C5	100nF	Decoupling capacitor
C6		

Table 53 – SMP-4 capacitors configuration

## 15. Standard information regarding manufacturability of Melexis products with different soldering processes

Our products are classified and qualified regarding soldering technology, solderability and moisture sensitivity level according to standards in place in Semiconductor industry.

For further details about test method references and for compliance verification of selected soldering method for product integration, Melexis recommends reviewing on our web site the General Guidelines soldering recommendation (<http://www.melexis.com/en/quality-environment/soldering>).

For all soldering technologies deviating from the one mentioned in above document (regarding peak temperature, temperature gradient, temperature profile etc), additional classification and qualification tests have to be agreed upon with Melexis.

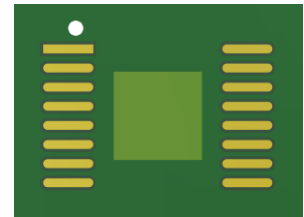
For package technology embedding trim and form post-delivery capability, Melexis recommends consulting the dedicated trim&forming recommendation application note: lead trimming and forming recommendations (<http://www.melexis.com/en/documents/documentation/application-notes/lead-trimming-and-forming-recommendations>).

Melexis is contributing to global environmental conservation by promoting lead free solutions. For more information on qualifications of RoHS compliant products (RoHS = European directive on the Restriction Of the use of certain Hazardous Substances) please visit the quality page on our website: <http://www.melexis.com/en/quality-environment>.

### 15.1. Soldering recommendations for the Exposed Pad (EP) in TSSOP-16

The MLX90425 in a TSSOP-16 stacked dice configuration comes with an exposed pad. This package is necessary to enable sufficient space for the die stacking. The exposed pad is **not** used to improve the thermal dissipation of the IC. Consequently, the ICs are isolated with regards to the exposed pad, both electrically and thermally. To guarantee product performance and electrical safety, the following guidelines shall be followed when designing the PCB.

A copper pad of adequate size shall be placed under the exposed pad on the PCB. For electrical safety and optimal EMC and noise performance, the copper pad on the PCB shall remain electrically inactive (not connected to any electrical net) and covered by solder mask. It is recommended not to solder the package exposed pad to the PCB.



When the exposed pad is soldered, the following remarks shall be taken into consideration:

- a stencil of minimal thickness of 150um shall be used
- when possible, dispensing shall be limited to two dots of 1mm diameter

a limited force of 1N to 2 N should be applied to the TSSOP package to secure wetting contact of the exposed pad to solder paste

## 16. ESD Precautions

Electronic semiconductor products are sensitive to electrostatic discharges (ESD).

Always observe electrostatic discharge control procedures whenever handling semiconductor products.



# MLX90425

## Triaxis® Position Sensor IC

Datasheet

### 17.1.3. SOIC-8 – Sensitive Spot Positioning

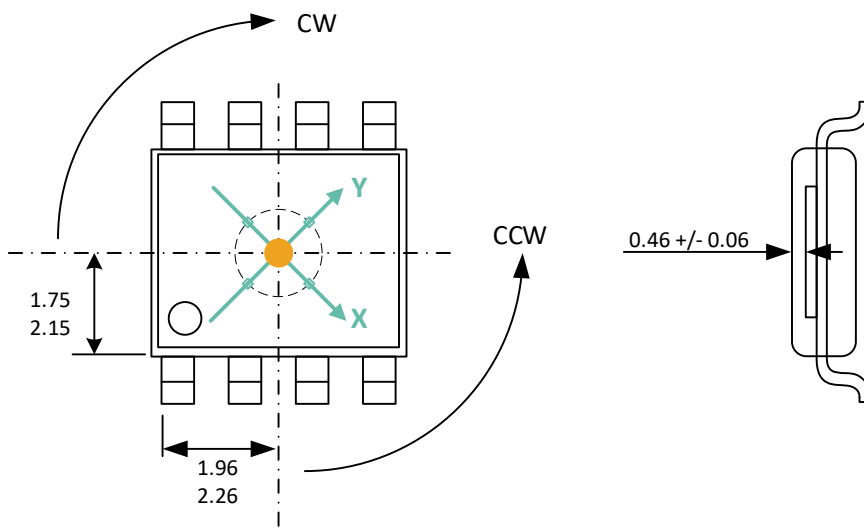
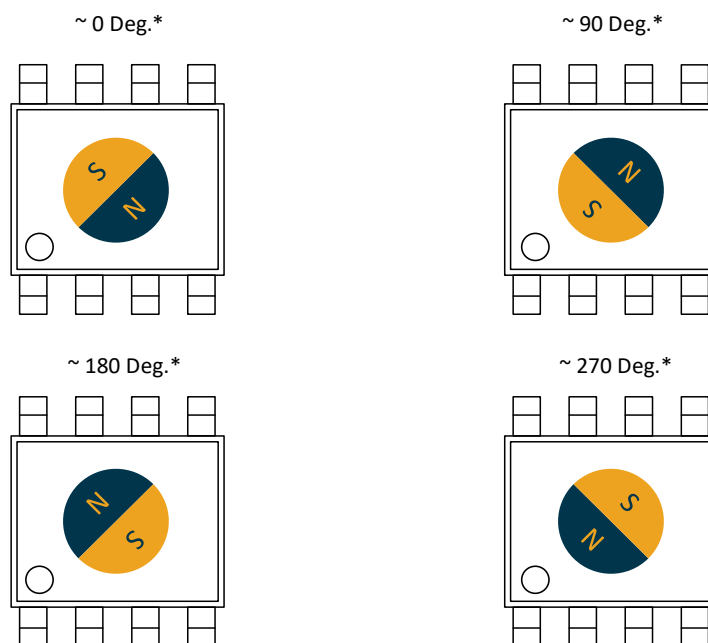


Figure 21 – SOIC-8 sensitive spot position

### 17.1.4. SOIC-8 – Angle Detection



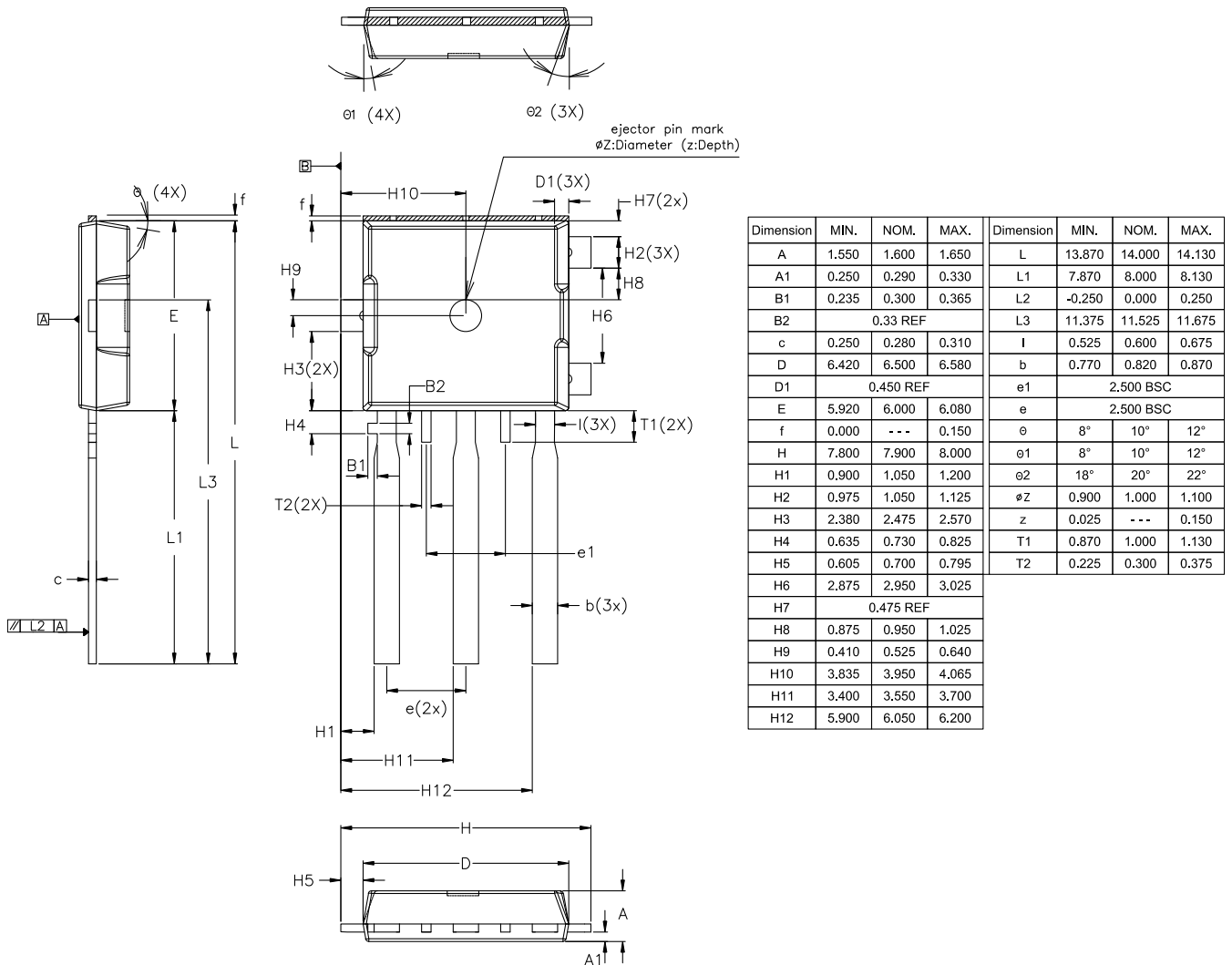
\* No absolute reference for the angular information.

Figure 22 – SOIC-8 angle detection

The MLX90425 is an absolute angular position sensor, but the linearity error (see section 8) does not include the error linked to the absolute reference 0 Deg. This reference can be fixed in the application through the discontinuity point.

## 17.2. SMP-3 – Package Information

### 17.2.1. SMP-3 – Package Outline Dimension (POD)



NOTES:

1. DIMENSIONS ARE IN MILLIMETER UNLESS NOTED OTHERWISE.

⚠ PACKAGE WIDTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15MM PER END. PACKAGE LENGTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25MM PER SIDE.

⚠ THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. PACKAGE WIDTH AND LENGTH ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH.

4. PLATING SPECS: MATTED TIN, ELECTROPLATED, 12 ± 5 MICROMETER (μm) THICKNESS

5. ALL "EARS" ARE CONNECTED TO ELECTRIC GROUND.

Figure 23 – SMP-3 package outline drawing

17.2.2. SMP-3 – Marking

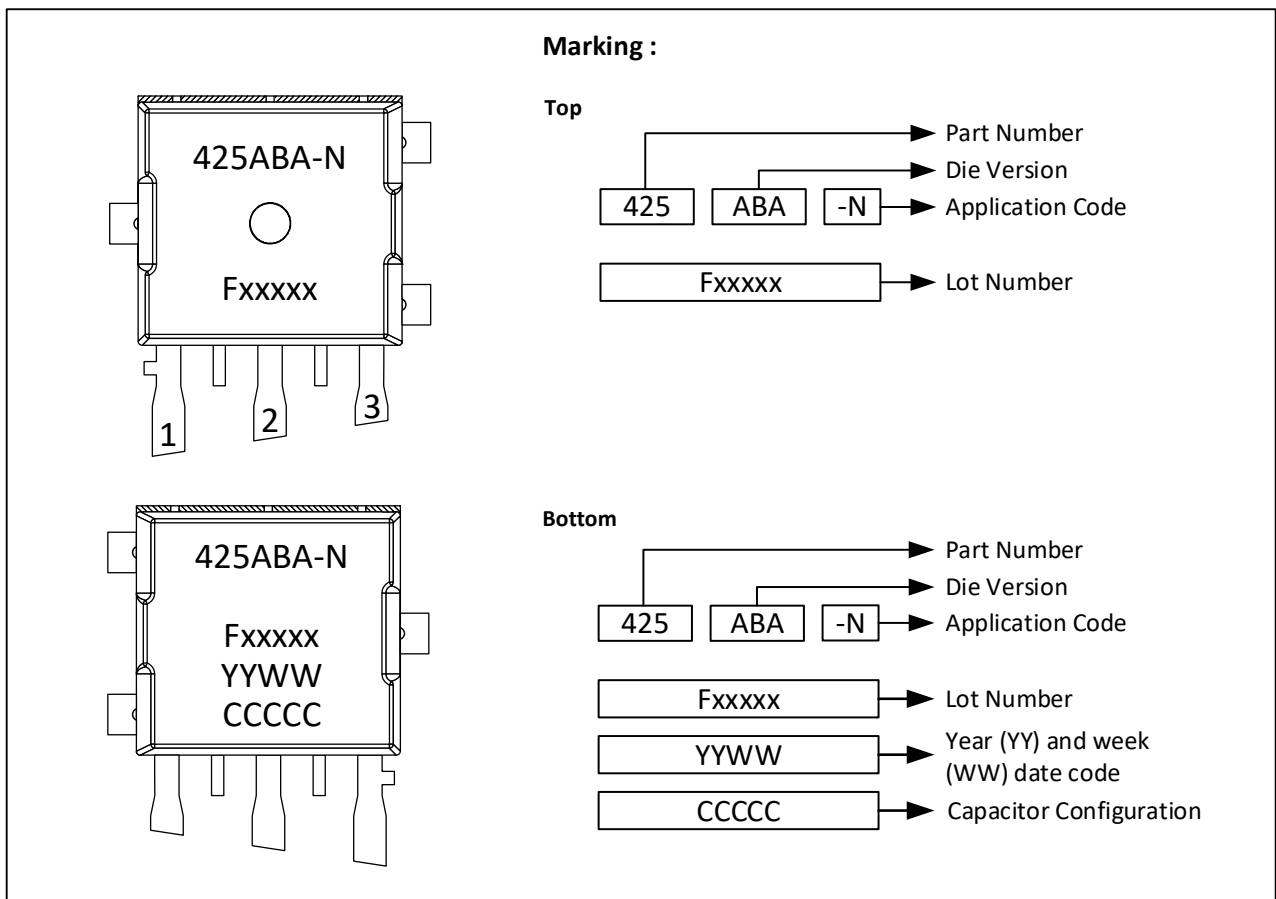


Figure 24 – SMP-3 marking

17.2.3. SMP-3 – Sensitive Spot Positioning

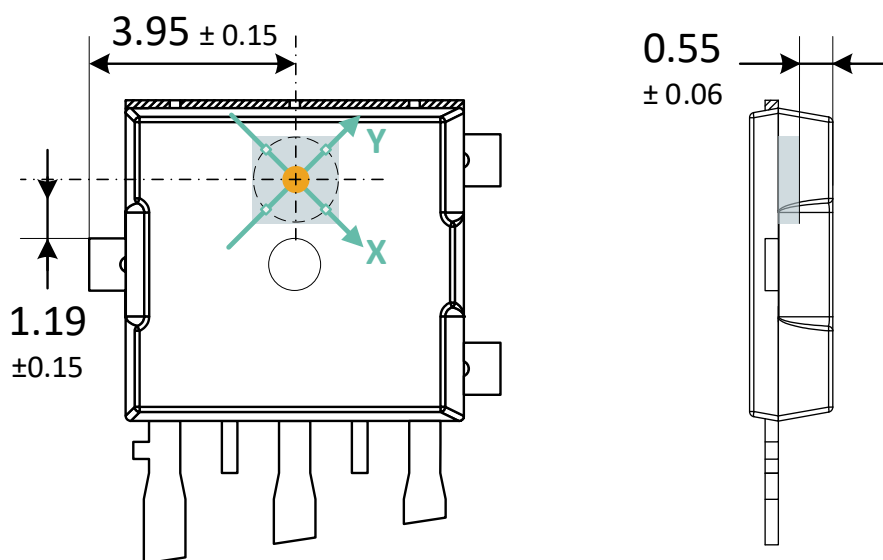


Figure 25 – SMP-3 sensitive spot position

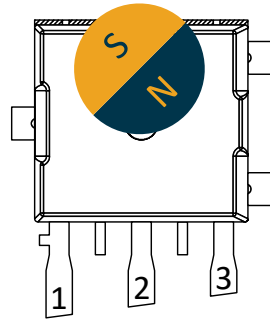
# MLX90425

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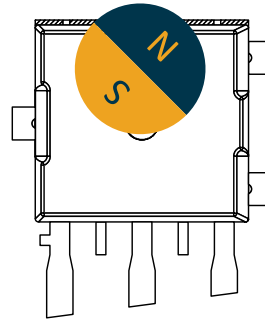
Datasheet

### 17.2.4. SMP-3 – Angle Detection

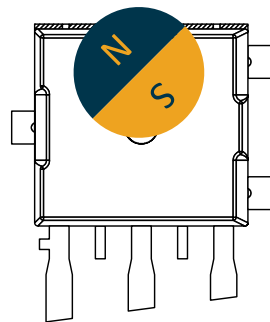
~ 0 Deg.\*



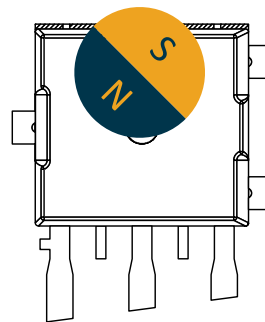
~ 90 Deg.\*



~ 180 Deg.\*



~ 270 Deg.\*



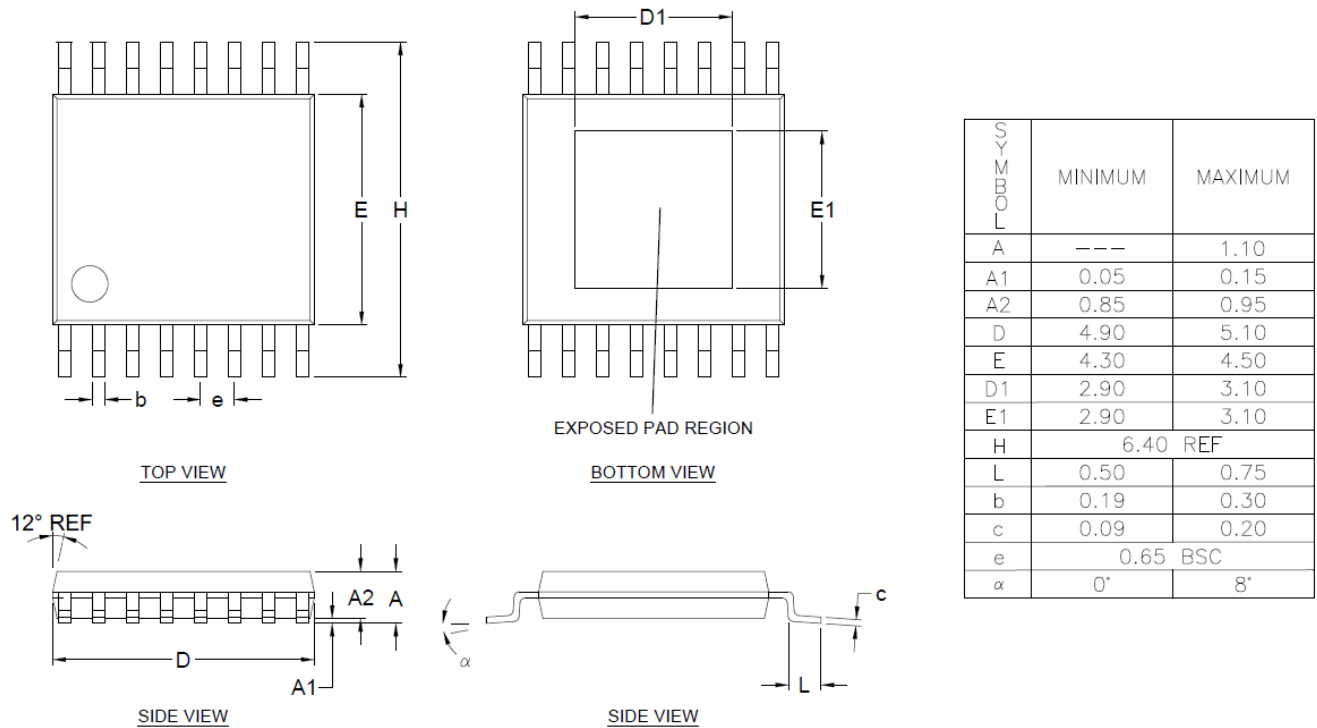
\* Not an absolute reference for the angular information

Figure 26 – SMP-3 angle detection

The MLX90425 is an absolute angular position sensor, but the linearity error (see section 8) does not include the error linked to the absolute reference 0 Deg. This reference can be fixed in the application through the discontinuity point.

### 17.3. TSSOP-16\_EP

#### 17.3.1. TSSOP-16\_EP- Package Outline Dimensions (POD)



NOTE :

1. ALL DIMENSIONS IN MILLIMETERS (mm) UNLESS OTHERWISE STATED.
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS OF MAX 0.15 mm PER SIDE.
3. DIMENSION E DOES NOT INCLUDE INTERLEADS FLASH OR PROTRUSIONS OF MAX 0.25 mm PER SIDE.
4. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION OF MAX 0.08 mm.
5. LEAD COPLANARITY SHALL BE MAXIMUM 0.1 mm.

Figure 27 – TSSOP-16\_EP Package Outline Dimensions

#### 17.3.2. TSSOP-16\_EP- Pinout and Marking

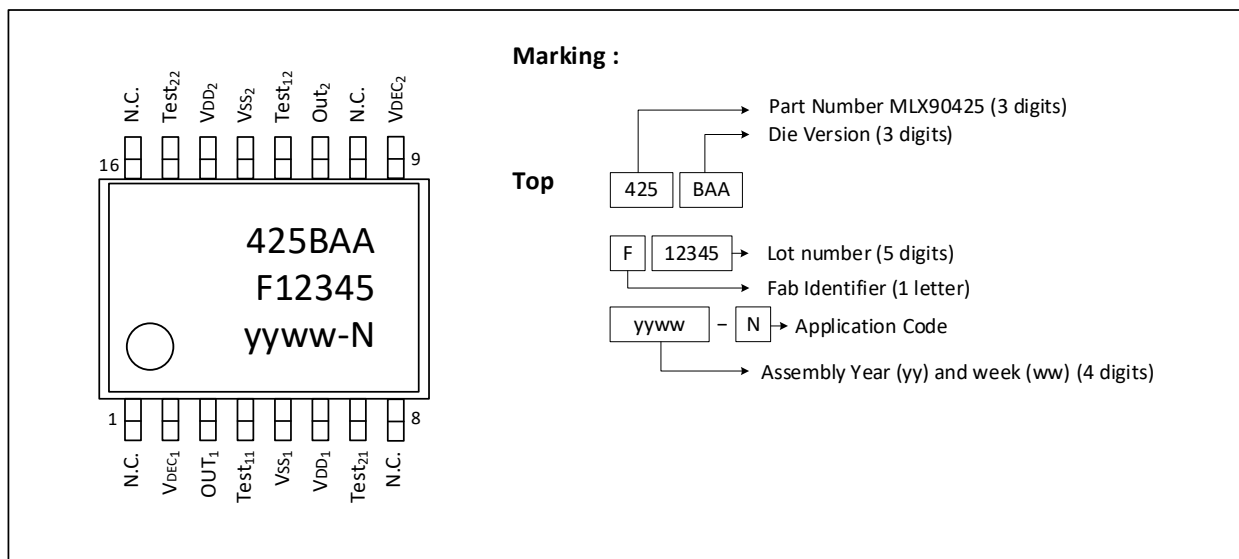


Figure 28 – TSSOP-16\_EP Pinout and Marking

17.3.3. TSSOP-16\_EP- Sensitive spot positioning

17.3.3.1. Rotary Stray-field Immune

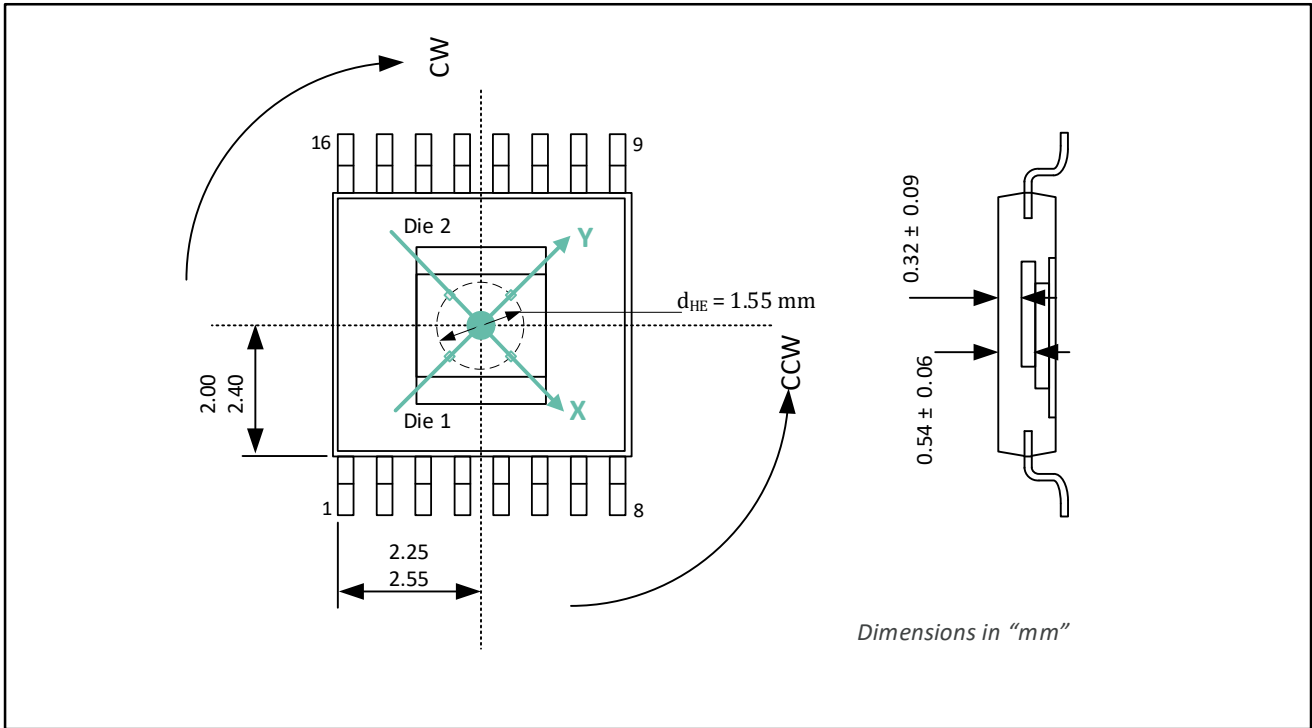


Figure 29 – TSSOP-16\_EP sensitive spot for rotary Stray-Field immune mode

# MLX90425

## Triaxis® Position Sensor IC

Datasheet

### 17.3.4. TSSOP-16\_EP- Angle detection

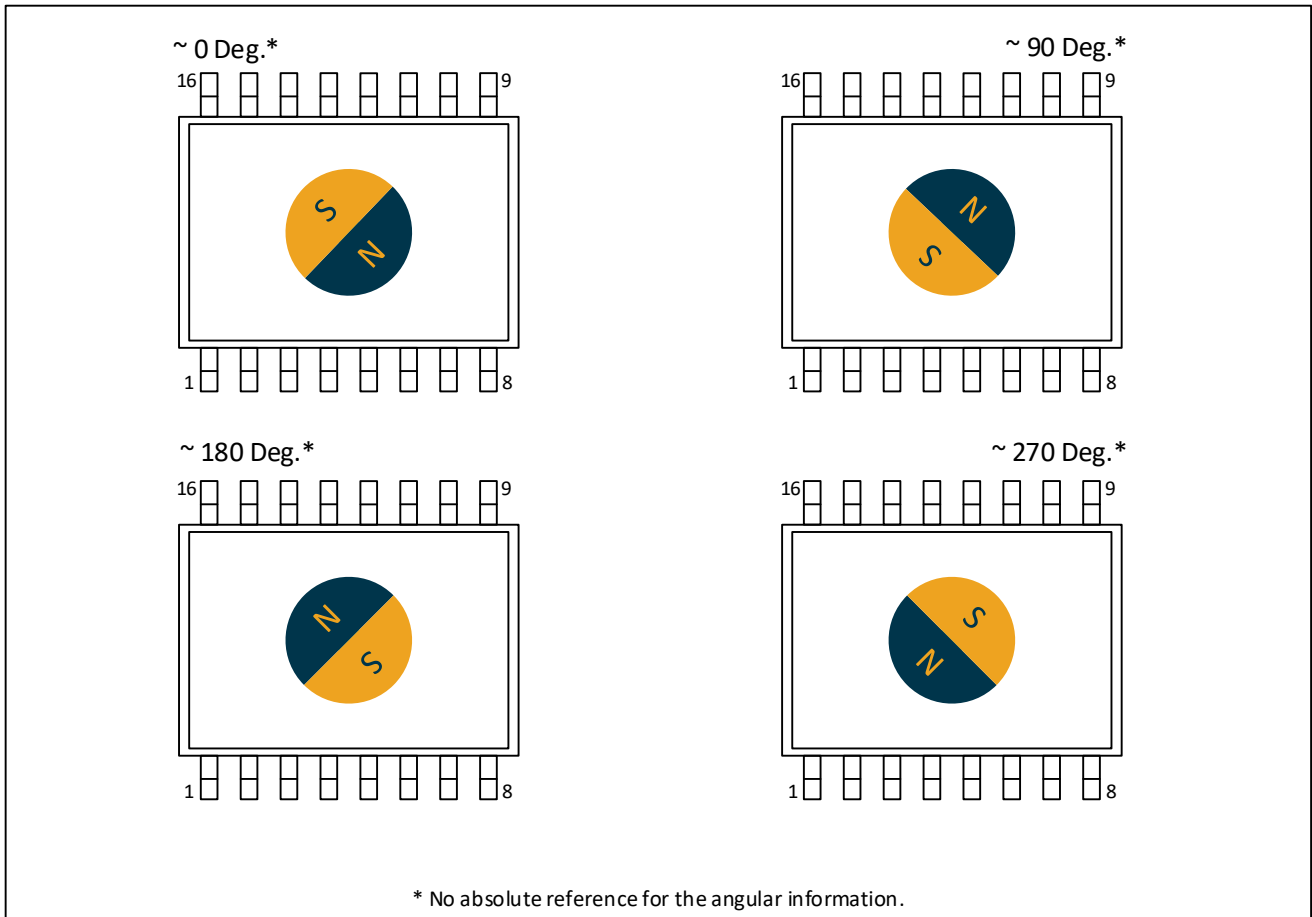


Figure 30 – TSSOP-16\_EP Angle Detection

The MLX90425 is an absolute angular position sensor but the linearity error (See section 8) does not include the error linked to the absolute reference 0 Deg. (which can be fixed in the application through the discontinuity point).

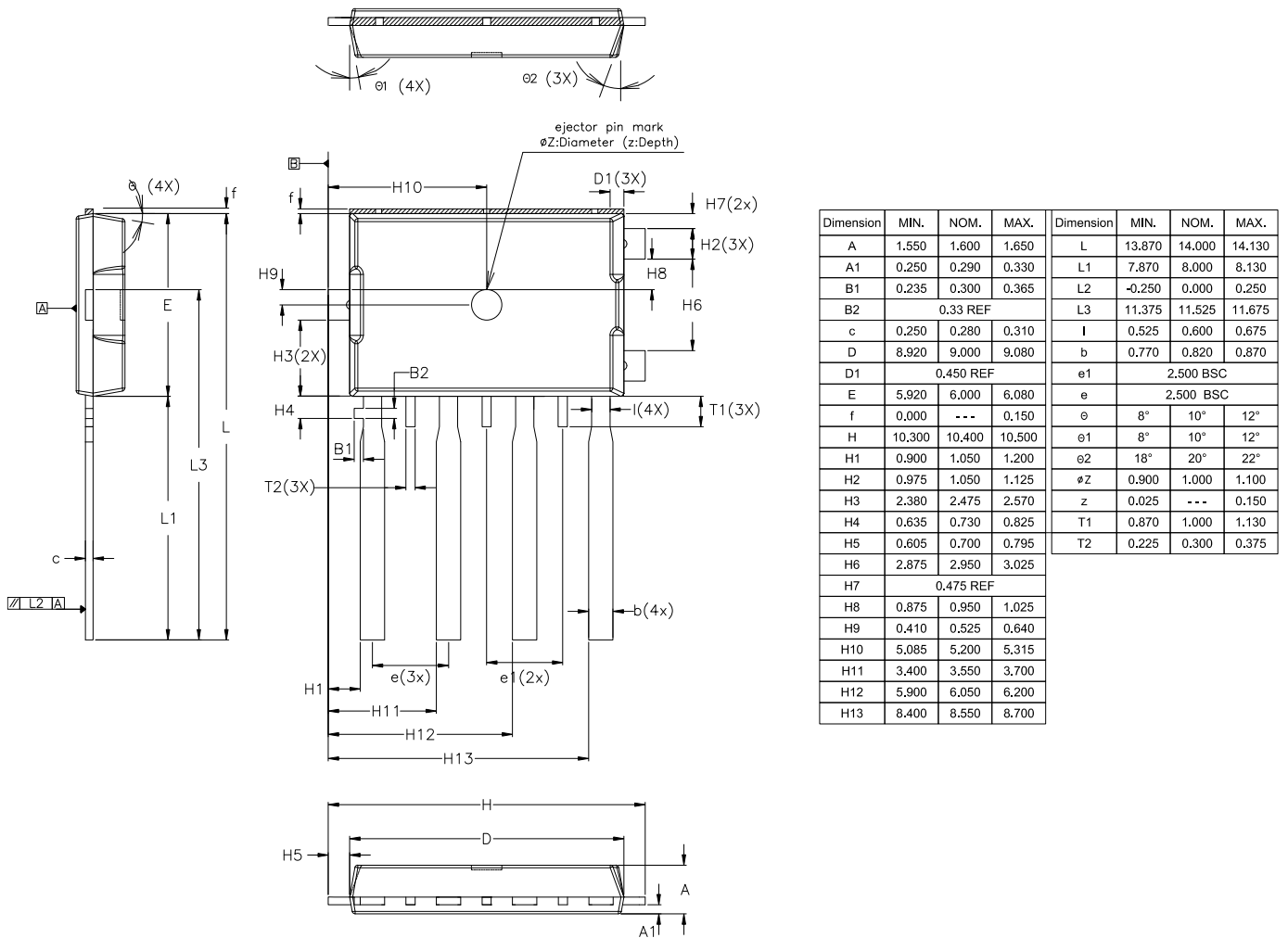
# MLX90425

## Triaxis® Position Sensor IC

Datasheet

### 17.4. SMP-4 Package Information

#### 17.4.1. SMP-4- Package Outline Dimensions (POD)



NOTES:

1. DIMENSIONS ARE IN MILLIMETER UNLESS NOTED OTHERWISE.

2. PACKAGE WIDTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15MM PER END. PACKAGE LENGTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25MM PER SIDE.

3. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. PACKAGE WIDTH AND LENGTH ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH.

4. PLATING SPECS: MATTED TIN, ELECTROPLATED, 12 ± 5 MICROMETER (µm) THICKNESS

5. ALL "EARS" ARE CONNECTED TO ELECTRIC GROUND.

Figure 31 – SMP-4 Package Outline Dimensions

### 17.4.2. SMP-4- Pinout and Marking

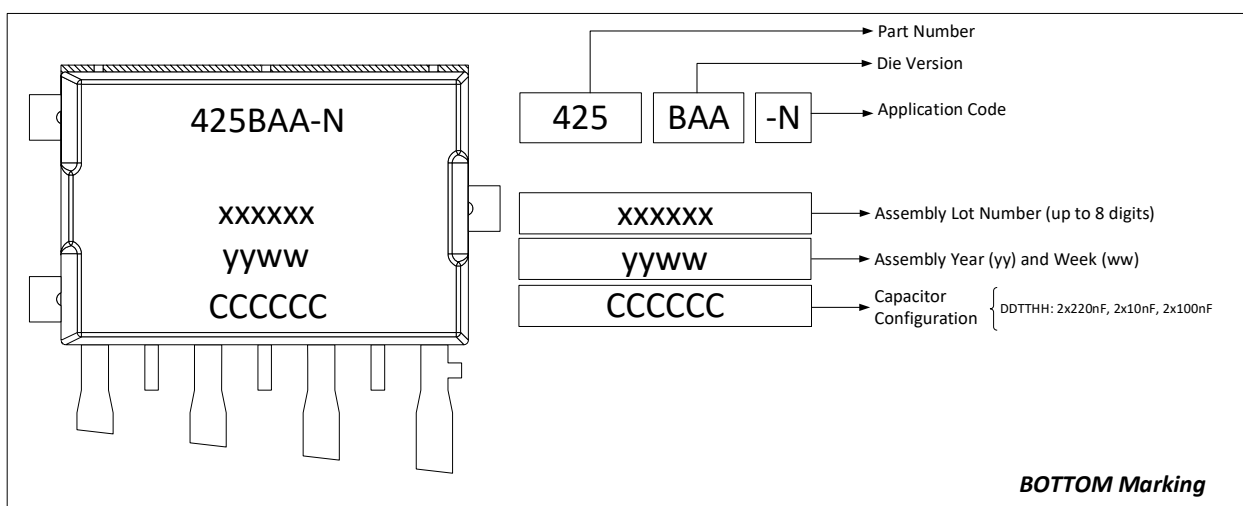
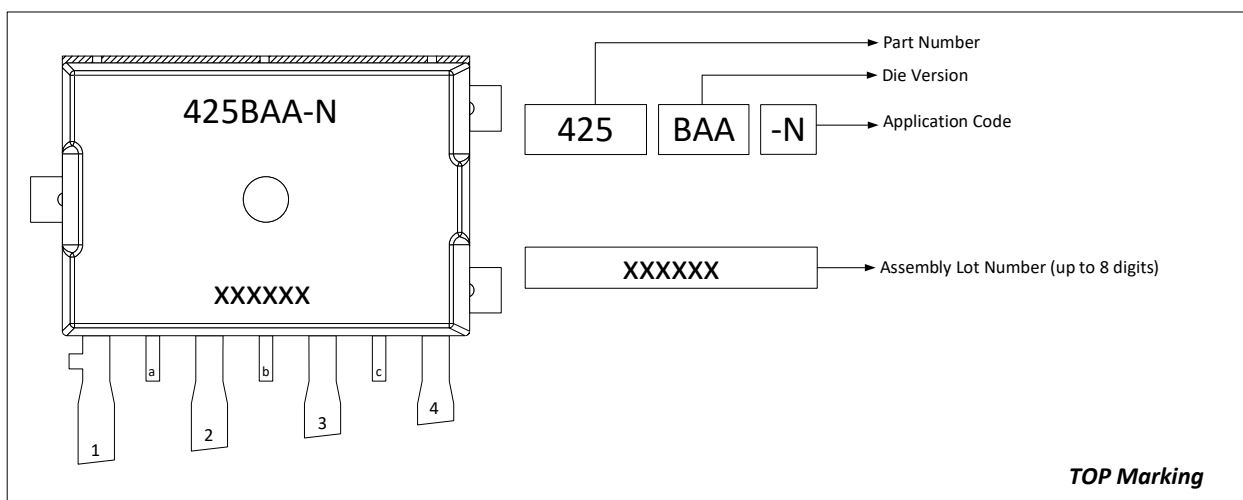


Figure 32 – SMP-4 Pinout and Marking

### 17.4.3. SMP-4- Sensitive spot positioning

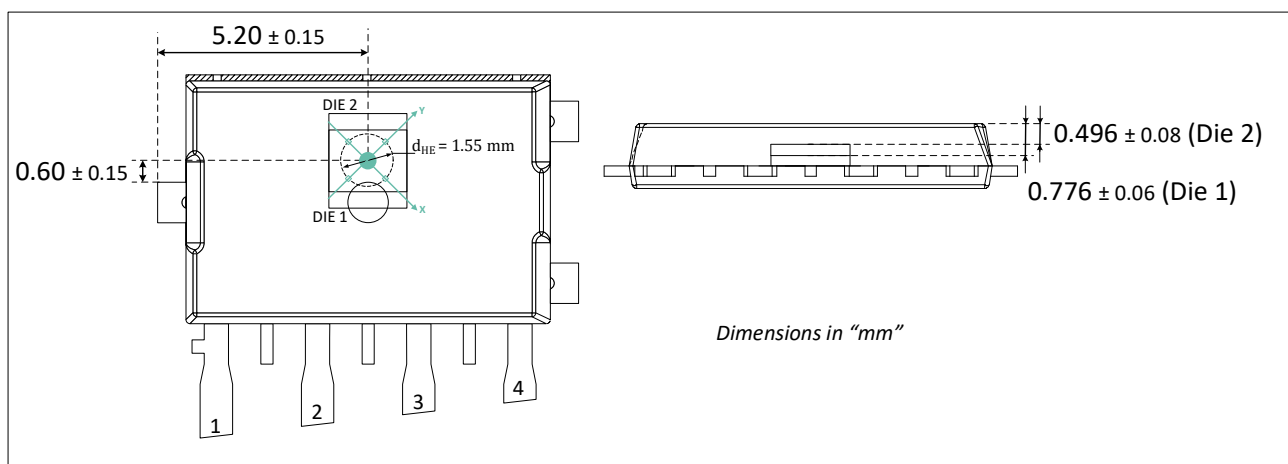


Figure 33 – SMP-4 sensitive spot for rotary Stray-Field immune mode

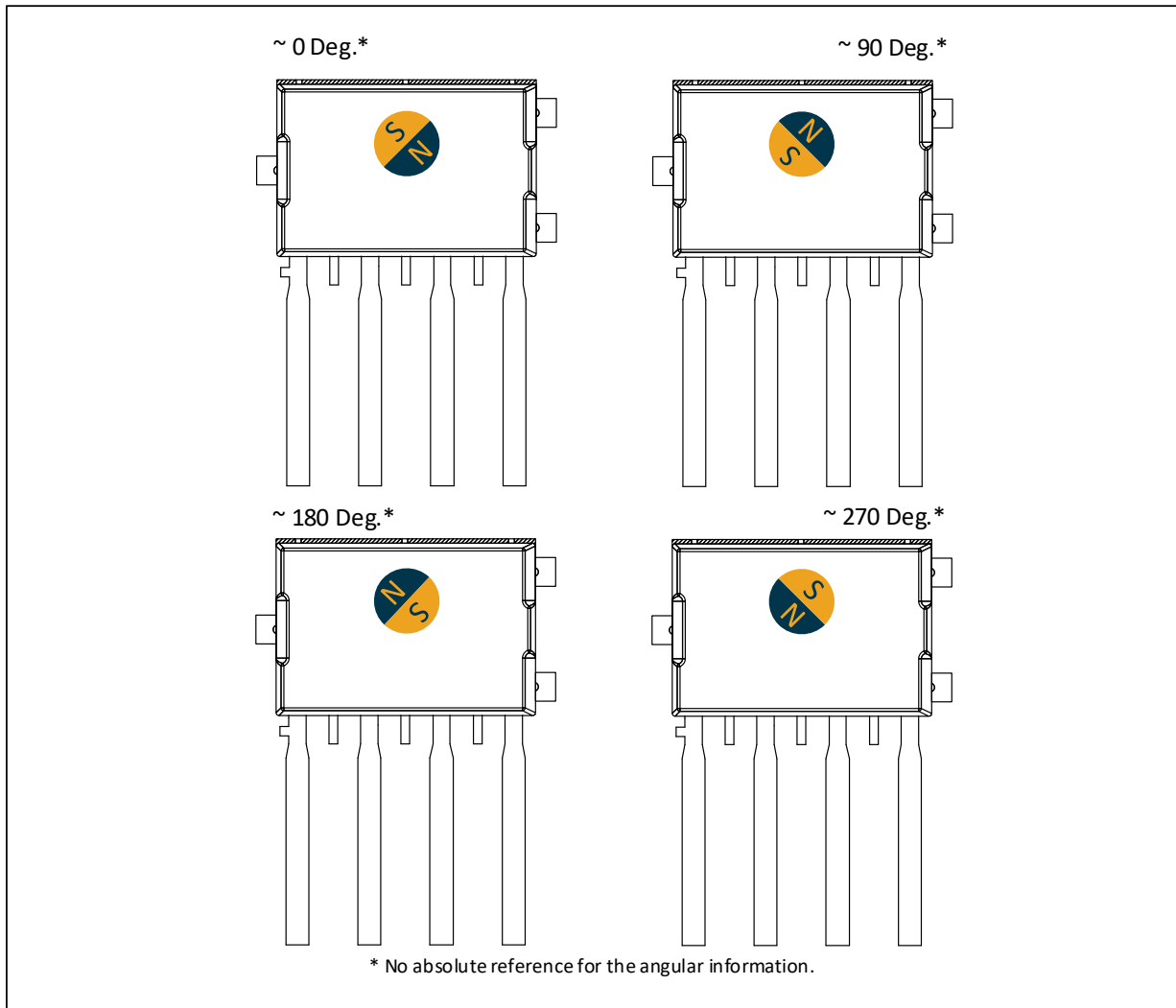


Figure 34 – SMP-4 Angle Detection

The MLX90425 is an absolute angular position sensor but the linearity error (See section 8) does not include the error linked to the absolute reference 0 Deg. (which can be fixed in the application through the discontinuity point).

## 17.5. Packages Thermal Performances

The table below describes the thermal behavior of available packages following JEDEC EIA/JESD 51.X standard.

Package	Junction to case - $\theta_{jc}$	Junction to ambient - $\theta_{ja}$ (JEDEC 1s2p board)	Junction to ambient - $\theta_{ja}$ (JEDEC 1s0p board)
SOIC-8	38.8 K/W	112 K/W	153 K/W
SMP-3	34.4 K/W	-	206 K/W <sup>(24)</sup>
TSSOP-16_EP	26 K/W	42 K/W	150 K/W
SMP-4	26 K/W	-	145 K/W <sup>(24)</sup>

*Table 54 – Standard packages thermal performances*

<sup>24</sup> PCB-less solutions have been evaluated in a typical application case. Values for these packages are given as informative.

## 18. Contact

For the latest version of this document, go to our website at [www.melexis.com/MLX90425](http://www.melexis.com/MLX90425).

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